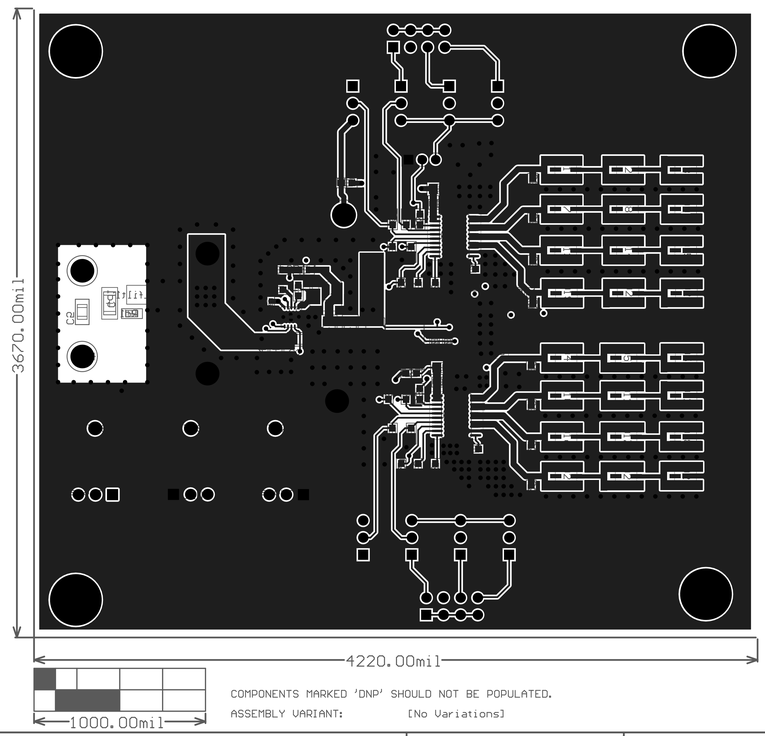
Layer	Name	Material	Thickness	Constant	Board Layer Stack
1	Top Overlay				
2	Top Solder	Solder Resist	0.40mil	3.5	
3	Component Side	Copper	1.42mil		
4	Dielectric 1	FR-4	12.00mil	4.2	
5	Ground Plane	Copper	1.42mil		
6	Dielectric 3	FR-4	32.00mil	4.2	
7	Signal Layer 1	Copper	1.42mil		
8	Dielectric 4	FR-4	12.00mil	4.2	
9	Solder Side	Copper	1.42mil		
10	Bottom Solder	Solder Resist	0.40mil	3.5	
11	Bottom Overlay				



COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.
ASSEMBLY VARIANT: [No Variations]

DESIGN INFORMATION

MIN. TRACK WIDTH: 8 MIL
MIN. CLEARANCE: 0.2 mm
MIN. VIA PAD SIZE: 24 MIL
MINIMUM ANNULAR RING 0.05mm (2MIL) EXTERNAL
PER IPC-D-275 CLASS 2 LEVEL C
REGISTRATION TOLERANCES: METAL +/- 5 MIL, HOLES +/- 3 MIL
HOLE SIZE TOLERANCE (UNLESS OTHERWISE SPECIFIED): +/- 3 MIL

MATERIAL:
[ ] FR-408 [X] FR-4 High Tg [ ] OTHER
THICKNESS: [X] 62 MIL (1.6mm) +/-10% [ ] OTHER
TOLERANCE: [X] ANSI IPC-6012 TYPE 3 CLASS 2
[ ] OTHER +/-
BOW & TWIST: [X] ANSI IPC-6012 TYPE 3 CLASS 2
[ ] OTHER +/-
DRILLING:
REFERENCE: [X] AS SHOWN [X] NC_DRILL FILES
PTH MIN COPPER THICKNESS: [X] 1MIL [ ] OTHER
BOARD FINISH:
SILKSCREEN: [X] TOP [X] BOTTOM
SILKSCREEN COLOR: [X] WHITE [ ] OTHER
SOLDER RESIST COLOR: [X] GREEN [ ] OTHER
[X] MATTE [ ] SEMI-GLOSS
SURFACE FINISH: [X] IMMERSION GOLD (ENIG) [ ] ENEPIG
[ ] IMM. TIN/SILVER OR EQUIV [ ] OTHER
ARRAY/PANEL: [ ] CUT AND TRIM PER M1 BOARD OUTLINE
[ ] N.C. ROUTE [X] V. SCORE
CERTIFICATION: MATERIALS AND WORKMANSHIP FOR ALL PCBS TO MEET OR EXCEED THE REQUIREMENTS OF:
[X] ANSI IPC-A-600F CLASS -> [ ] 1 [X] 2 [ ] 3
[X] UL 94V-0 [X] RoHS [ ] OTHER PER ORDER
ADDITIONAL REQUIREMENTS:
MICROSECTION: [ ] YES
BARE BOARD ELEC. TEST: [ ] NONE [X] REQUIRED [ ] PER ORDER
MANUFACTURER'S UL: [ ] RAIL [ ] METAL [X] SILK

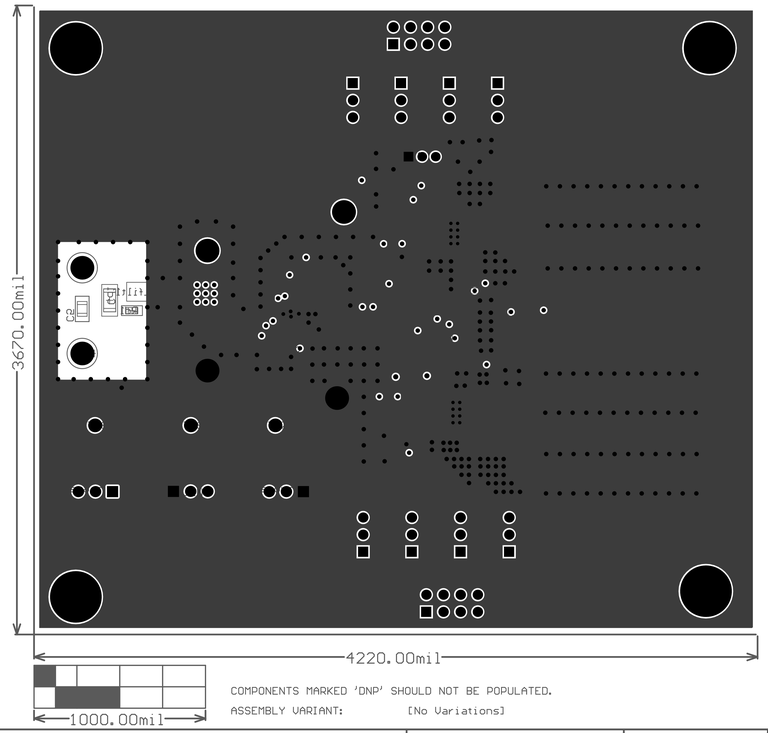
TEXAS INSTRUMENTS

PROJECT TITLE: LM5360ONAEVM/O1LAEVM
DESIGNED FOR: Public Release
FILE NAME: TIDA01348.PcbDoc

PCB VIEWED FROM TOP SIDE	BOARD #: TIDA-01348	REV: A	SUN REV: Not In VersionControl
LAYER NAME =	TID #: TIDA-01348		
PLOT NAME = Component Side	GENERATED : 9/26/2016 3:37:38 PM	TEXAS INSTRUMENTS	

ENGINEER:	LAYOUT BY:
Robert Blattner	Robert Blattner
SCALE: 1.00	ALTIUM DESIGNER VERSION: 16.0.9.368

Layer	Name	Material	Thickness	Constant	Board Layer Stack
1	Top Overlay				
2	Top Solder	Solder Resist	0.40mil	3.5	
3	Component Side	Copper	1.42mil		
4	Dielectric 1	FR-4	12.00mil	4.2	
5	Ground Plane	Copper	1.42mil		
6	Dielectric 3	FR-4	32.00mil	4.2	
7	Signal Layer 1	Copper	1.42mil		
8	Dielectric 4	FR-4	12.00mil	4.2	
9	Solder Side	Copper	1.42mil		
10	Bottom Solder	Solder Resist	0.40mil	3.5	
11	Bottom Overlay				



COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.
ASSEMBLY VARIANT: [No Variations]

DESIGN INFORMATION

MIN. TRACK WIDTH: 8 MIL
MIN. CLEARANCE: 0.2 mm
MIN. VIA PAD SIZE: 24 MIL
MINIMUM ANNULAR RING 0.05mm (2MIL) EXTERNAL
PER IPC-D-275 CLASS 2 LEVEL C
REGISTRATION TOLERANCES: METAL +/- 5 MIL, HOLES +/- 3 MIL
HOLE SIZE TOLERANCE (UNLESS OTHERWISE SPECIFIED): +/- 3 MIL

MATERIAL:
[ ] FR-408 [X] FR-4 High Tg [ ] OTHER
THICKNESS: [X] 62 MIL (1.6mm) +/-10% [ ] OTHER
TOLERANCE: [X] ANSI IPC-6012 TYPE 3 CLASS 2
[ ] OTHER +/-
BOW & TWIST: [X] ANSI IPC-6012 TYPE 3 CLASS 2
[ ] OTHER +/-
DRILLING:
REFERENCE: [X] AS SHOWN [X] NC_DRILL FILES
PTH MIN COPPER THICKNESS: [X] 1MIL [ ] OTHER
BOARD FINISH:
SILKSCREEN: [X] TOP [X] BOTTOM
SILKSCREEN COLOR: [X] WHITE [ ] OTHER
SOLDER RESIST COLOR: [X] GREEN [ ] OTHER
[X] MATTE [ ] SEMI-GLOSS
SURFACE FINISH: [X] IMMERSION GOLD (ENIG) [ ] ENEPIG
[ ] IMM. TIN/SILVER OR EQUIV [ ] OTHER
ARRAY/PANEL: [ ] CUT AND TRIM PER M1 BOARD OUTLINE
[ ] N.C. ROUTE [X] V. SCORE
CERTIFICATION: MATERIALS AND WORKMANSHIP FOR ALL PCBS TO MEET OR EXCEED THE REQUIREMENTS OF:
[X] ANSI IPC-A-600F CLASS -> [ ] 1 [X] 2 [ ] 3
[X] UL 94V-0 [X] RoHS [ ] OTHER PER ORDER
ADDITIONAL REQUIREMENTS:
MICROSECTION: [ ] YES
BARE BOARD ELEC. TEST: [ ] NONE [X] REQUIRED [ ] PER ORDER
MANUFACTURER'S UL: [ ] RAIL [ ] METAL [X] SILK

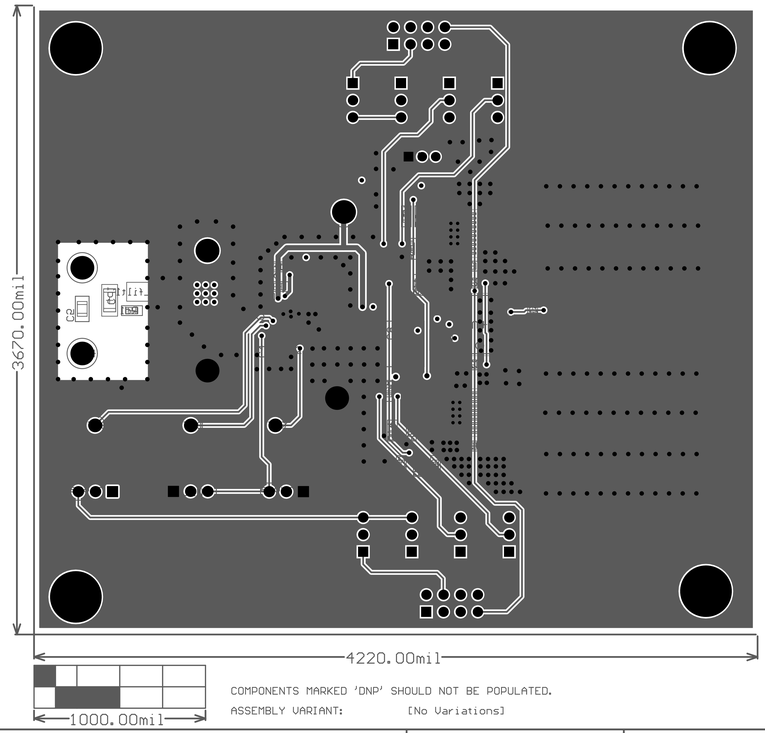
TEXAS INSTRUMENTS

PROJECT TITLE: LM5360ONAEVM/O1LAEVM
DESIGNED FOR: Public Release
FILE NAME: TIDA01348.PcbDoc

PCB VIEWED FROM TOP SIDE	BOARD #: TIDA-01348	REV: A	SVN REV: Not In VersionControl
LAYER NAME =	TID #: TIDA-01348		
PLOT NAME = MidLayer1	GENERATED : 9/26/2016 3:37:40 PM		TEXAS INSTRUMENTS

ENGINEER: Robert Blattner	LAYOUT BY: Robert Blattner
SCALE: 1.00	ALTIUM DESIGNER VERSION: 16.0.9.368

Layer	Name	Material	Thickness	Constant	Board Layer Stack
1	Top Overlay				
2	Top Solder	Solder Resist	0.40mil	3.5	
3	Component Side	Copper	1.42mil		
4	Dielectric 1	FR-4	12.00mil	4.2	
5	Ground Plane	Copper	1.42mil		
6	Dielectric 3	FR-4	32.00mil	4.2	
7	Signal Layer 1	Copper	1.42mil		
8	Dielectric 4	FR-4	12.00mil	4.2	
9	Solder Side	Copper	1.42mil		
10	Bottom Solder	Solder Resist	0.40mil	3.5	
11	Bottom Overlay				



COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.
ASSEMBLY VARIANT: [No Variations]

DESIGN INFORMATION

MIN. TRACK WIDTH: 8 MIL
MIN. CLEARANCE: 0.2 mm
MIN. VIA PAD SIZE: 24 MIL
MINIMUM ANNULAR RING 0.05mm (2MIL) EXTERNAL
PER IPC-D-275 CLASS 2 LEVEL C
REGISTRATION TOLERANCES: METAL +/- 5 MIL, HOLES +/- 3 MIL
HOLE SIZE TOLERANCE (UNLESS OTHERWISE SPECIFIED): +/- 3 MIL

MATERIAL:
[ ] FR-408 [X] FR-4 High Tg [ ] OTHER
THICKNESS: [X] 62 MIL (1.6mm) +/-10% [ ] OTHER
TOLERANCE: [X] ANSI IPC-6012 TYPE 3 CLASS 2
[ ] OTHER +/-
BOW & TWIST: [X] ANSI IPC-6012 TYPE 3 CLASS 2
[ ] OTHER +/-
DRILLING:
REFERENCE: [X] AS SHOWN [X] NC_DRILL FILES
PTH MIN COPPER THICKNESS: [X] 1MIL [ ] OTHER
BOARD FINISH:
SILKSCREEN: [X] TOP [X] BOTTOM
SILKSCREEN COLOR: [X] WHITE [ ] OTHER
SOLDER RESIST COLOR: [X] GREEN [ ] OTHER
[X] MATTE [ ] SEMI-GLOSS
SURFACE FINISH: [X] IMMERSION GOLD (ENIG) [ ] ENEPIG
[ ] IMM. TIN/SILVER OR EQUIV [ ] OTHER
ARRAY/PANEL: [ ] CUT AND TRIM PER M1 BOARD OUTLINE
[ ] N.C. ROUTE [X] V. SCORE
CERTIFICATION: MATERIALS AND WORKMANSHIP FOR ALL PCBS TO MEET OR EXCEED THE REQUIREMENTS OF:
[X] ANSI IPC-A-600F CLASS -> [ ] 1 [X] 2 [ ] 3
[X] UL 94V-0 [X] RoHS [ ] OTHER PER ORDER
ADDITIONAL REQUIREMENTS:
MICROSECTION: [ ] YES
BARE BOARD ELEC. TEST: [ ] NONE [X] REQUIRED [ ] PER ORDER
MANUFACTURER'S UL: [ ] RAIL [ ] METAL [X] SILK

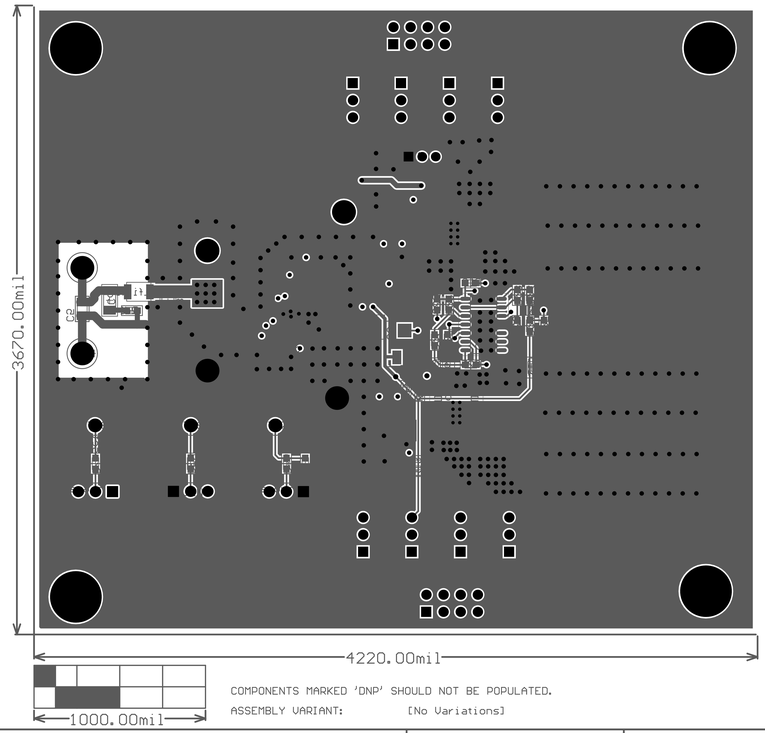
TEXAS INSTRUMENTS

PROJECT TITLE: LM5360ONAEVM/O1LAEVM
DESIGNED FOR: Public Release
FILE NAME: TIDA01348.PcbDoc

PCB VIEWED FROM TOP SIDE	BOARD #: TIDA-01348	REV: A	SVN REV: Not In VersionControl
LAYER NAME =	TID #: TIDA-01348		
PLOT NAME = Mid-Layer 2	GENERATED : 9/26/2016 3:37:45 PM	TEXAS INSTRUMENTS	

ENGINEER: Robert Blattner	LAYOUT BY: Robert Blattner
SCALE: 1.00	ALTIUM DESIGNER VERSION: 16.0.9.368

Layer	Name	Material	Thickness	Constant	Board Layer Stack
1	Top Overlay				
2	Top Solder	Solder Resist	0.40mil	3.5	
3	Component Side	Copper	1.42mil		
4	Dielectric 1	FR-4	12.00mil	4.2	
5	Ground Plane	Copper	1.42mil		
6	Dielectric 3	FR-4	32.00mil	4.2	
7	Signal Layer 1	Copper	1.42mil		
8	Dielectric 4	FR-4	12.00mil	4.2	
9	Solder Side	Copper	1.42mil		
10	Bottom Solder	Solder Resist	0.40mil	3.5	
11	Bottom Overlay				



COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.
ASSEMBLY VARIANT: [No Variations]

DESIGN INFORMATION

MIN. TRACK WIDTH: 8 MIL
MIN. CLEARANCE: 0.2 mm
MIN. VIA PAD SIZE: 24 MIL
MINIMUM ANNULAR RING 0.05mm (2MIL) EXTERNAL
PER IPC-D-275 CLASS 2 LEVEL C
REGISTRATION TOLERANCES: METAL +/- 5 MIL, HOLES +/- 3 MIL
HOLE SIZE TOLERANCE (UNLESS OTHERWISE SPECIFIED): +/- 3 MIL

MATERIAL:
[ ] FR-408 [X] FR-4 High Tg [ ] OTHER
THICKNESS: [X] 62 MIL (1.6mm) +/-10% [ ] OTHER
TOLERANCE: [X] ANSI IPC-6012 TYPE 3 CLASS 2
[ ] OTHER +/-
BOW & TWIST: [X] ANSI IPC-6012 TYPE 3 CLASS 2
[ ] OTHER +/-
DRILLING:
REFERENCE: [X] AS SHOWN [X] NC_DRILL FILES
PTH MIN COPPER THICKNESS: [X] 1MIL [ ] OTHER
BOARD FINISH:
SILKSCREEN: [X] TOP [X] BOTTOM
SILKSCREEN COLOR: [X] WHITE [ ] OTHER
SOLDER RESIST COLOR: [X] GREEN [ ] OTHER
[X] MATTE [ ] SEMI-GLOSS
SURFACE FINISH: [X] IMMERSION GOLD (ENIG) [ ] ENEPIG
[ ] IMM. TIN/SILVER OR EQUIV [ ] OTHER
ARRAY/PANEL: [ ] CUT AND TRIM PER M1 BOARD OUTLINE
[ ] N.C. ROUTE [X] V. SCORE
CERTIFICATION: MATERIALS AND WORKMANSHIP FOR ALL PCBS TO MEET OR EXCEED THE REQUIREMENTS OF:
[X] ANSI IPC-A-600F CLASS -> [ ] 1 [X] 2 [ ] 3
[X] UL 94V-0 [X] RoHS [ ] OTHER PER ORDER
ADDITIONAL REQUIREMENTS:
MICROSECTION: [ ] YES
BARE BOARD ELEC. TEST: [ ] NONE [X] REQUIRED [ ] PER ORDER
MANUFACTURER'S UL: [ ] RAIL [ ] METAL [X] SILK

TEXAS INSTRUMENTS

PROJECT TITLE: LM5360ONAEVM/O1LAEVM
DESIGNED FOR: Public Release
FILE NAME: TIDA01348.PcbDoc

PCB VIEWED FROM TOP SIDE	BOARD #: TIDA-01348	REV: A	SUN REV: Not In VersionControl
LAYER NAME =	TID #: TIDA-01348		
PLOT NAME = Solder Side	GENERATED : 9/26/2016 3:37:48 PM	TEXAS INSTRUMENTS	

ENGINEER: Robert Blattner	LAYOUT BY: Robert Blattner
SCALE: 1.00	ALTIUM DESIGNER VERSION: 16.0.9.368

Layer	Name	Material	Thickness	Constant	Board Layer Stack
1	Top Overlay				
2	Top Solder	Solder Resist	0.40mil	3.5	
3	Component Side	Copper	1.42mil		
4	Dielectric 1	FR-4	12.00mil	4.2	
5	Ground Plane	Copper	1.42mil		
6	Dielectric 3	FR-4	32.00mil	4.2	
7	Signal Layer 1	Copper	1.42mil		
8	Dielectric 4	FR-4	12.00mil	4.2	
9	Solder Side	Copper	1.42mil		
10	Bottom Solder	Solder Resist	0.40mil	3.5	
11	Bottom Overlay				

DESIGN INFORMATION

MIN. TRACK WIDTH: 8 MIL

MIN. CLEARANCE: 0.2 mm

MIN. VIA PAD SIZE: 24 MIL

MINIMUM ANNULAR RING 0.05mm (2MIL) EXTERNAL

PER IPC-D-275 CLASS 2 LEVEL C

REGISTRATION TOLERANCES: METAL +/- 5 MIL, HOLES +/- 3 MIL

HOLE SIZE TOLERANCE (UNLESS OTHERWISE SPECIFIED): +/- 3 MIL

MATERIAL:

[ ] FR-408 [X] FR-4 High Tg [ ] OTHER _____

THICKNESS: [X] 62 MIL (1.6mm) +/-10% [ ] OTHER _____

TOLERANCE: [X] ANSI IPC-6012 TYPE 3 CLASS 2

[ ] OTHER +/- _____

BOW & TWIST: [X] ANSI IPC-6012 TYPE 3 CLASS 2

[ ] OTHER +/- _____

DRILLING:

REFERENCE: [X] AS SHOWN [X] NC_DRILL FILES

PTH MIN COPPER THICKNESS: [X] 1MIL [ ] OTHER _____

BOARD FINISH:

SILKSCREEN: [X] TOP [X] BOTTOM

SILKSCREEN COLOR: [X] WHITE [ ] OTHER _____

SOLDER RESIST COLOR: [X] GREEN [ ] OTHER _____

[X] MATTE [ ] SEMI-GLOSS

SURFACE FINISH: [X] IMMERSION GOLD (ENIG) [ ] ENEPIG

[ ] IMM. TIN/SILVER OR EQUIV [ ] OTHER _____

ARRAY/PANEL: [ ] CUT AND TRIM PER M1 BOARD OUTLINE

[ ] N.C. ROUTE [X] V. SCORE

CERTIFICATION: MATERIALS AND WORKMANSHIP FOR ALL PCBS TO MEET OR EXCEED THE REQUIREMENTS OF:

[X] ANSI IPC-A-600F CLASS -> [ ] 1 [X] 2 [ ] 3

[X] UL 94V-0 [X] RoHS [ ] OTHER PER ORDER

ADDITIONAL REQUIREMENTS:

MICROSECTION: [ ] YES

BARE BOARD ELEC. TEST: [ ] NONE [X] REQUIRED [ ] PER ORDER

MANUFACTURER'S UL: [ ] RAIL [ ] METAL [X] SILK

SH-J1 SH-J2 SH-J3

COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.

ASSEMBLY VARIANT: [No Variations]

TEXAS INSTRUMENTS

PROJECT TITLE: LM53600NAEVM/O1LAEVM

DESIGNED FOR: Public Release

FILE NAME: TIDA01348.PcbDoc

PCB VIEWED FROM TOP SIDE	BOARD #: TIDA-01348	REV: A	SVN REV: Not In VersionControl	
LAYER NAME =	TID #: TIDA-01348			
PLOT NAME = Top Silkscreen Overlay	GENERATED : 9/26/2016 3:37:58 PM		TEXAS INSTRUMENTS	

ENGINEER:	LAYOUT BY:
Robert Blattner	Robert Blattner
SCALE: 1.00	ALTIUM DESIGNER VERSION: 16.0.9.368

Layer	Name	Material	Thickness	Constant	Board Layer Stack
1	Top Overlay				
2	Top Solder	Solder Resist	0.40mil	3.5	
3	Component Side	Copper	1.42mil		
4	Dielectric 1	FR-4	12.00mil	4.2	
5	Ground Plane	Copper	1.42mil		
6	Dielectric 3	FR-4	32.00mil	4.2	
7	Signal Layer 1	Copper	1.42mil		
8	Dielectric 4	FR-4	12.00mil	4.2	
9	Solder Side	Copper	1.42mil		
10	Bottom Solder	Solder Resist	0.40mil	3.5	
11	Bottom Overlay				

DESIGN INFORMATION

MIN. TRACK WIDTH: 8 MIL

MIN. CLEARANCE: 0.2 mm

MIN. VIA PAD SIZE: 24 MIL

MINIMUM ANNULAR RING 0.05mm (2MIL) EXTERNAL

PER IPC-D-275 CLASS 2 LEVEL C

REGISTRATION TOLERANCES: METAL +/- 5 MIL, HOLES +/- 3 MIL

HOLE SIZE TOLERANCE (UNLESS OTHERWISE SPECIFIED): +/- 3 MIL

MATERIAL:

[ ] FR-408 [X] FR-4 High Tg [ ] OTHER _____

THICKNESS: [X] 62 MIL (1.6mm) +/-10% [ ] OTHER _____

TOLERANCE: [X] ANSI IPC-6012 TYPE 3 CLASS 2

[ ] OTHER +/- _____

BOW & TWIST: [X] ANSI IPC-6012 TYPE 3 CLASS 2

[ ] OTHER +/- _____

DRILLING:

REFERENCE: [X] AS SHOWN [X] NC_DRILL FILES

PTH MIN COPPER THICKNESS: [X] 1MIL [ ] OTHER _____

BOARD FINISH:

SILKSCREEN: [X] TOP [X] BOTTOM

SILKSCREEN COLOR: [X] WHITE [ ] OTHER _____

SOLDER RESIST COLOR: [X] GREEN [ ] OTHER _____

[X] MATTE [ ] SEMI-GLOSS

SURFACE FINISH: [X] IMMERSION GOLD (ENIG) [ ] ENEPIG

[ ] IMM. TIN/SILVER OR EQUIV [ ] OTHER _____

ARRAY/PANEL: [ ] CUT AND TRIM PER M1 BOARD OUTLINE

[ ] N.C. ROUTE [X] V. SCORE

CERTIFICATION: MATERIALS AND WORKMANSHIP FOR ALL PCBS TO MEET OR EXCEED THE REQUIREMENTS OF:

[X] ANSI IPC-A-600F CLASS -> [ ] 1 [X] 2 [ ] 3

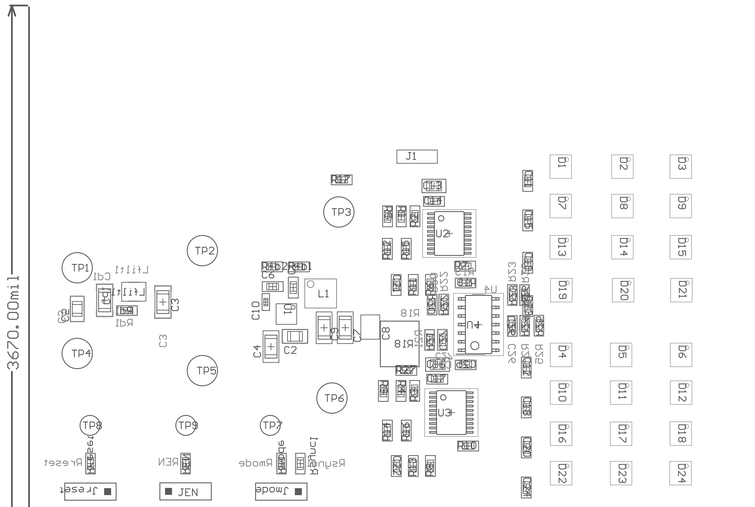
[X] UL 94V-0 [X] RoHS [ ] OTHER PER ORDER

ADDITIONAL REQUIREMENTS:

MICROSECTION: [ ] YES

BARE BOARD ELEC. TEST: [ ] NONE [X] REQUIRED [ ] PER ORDER

MANUFACTURER'S UL: [ ] RAIL [ ] METAL [X] SILK



COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.

ASSEMBLY VARIANT: [No Variations]

TEXAS INSTRUMENTS

PROJECT TITLE: LM53600NAEVM/01LAEVM

DESIGNED FOR: Public Release

FILE NAME: TIDA01348.PcbDoc

PCB VIEWED FROM TOP SIDE	BOARD #: TIDA-01348	REV: A	SVN REV: Not In VersionControl
LAYER NAME =	TID #: TIDA-01348		
PLOT NAME = Bottom Silkscreen Overlay	GENERATED : 9/26/2016 3:37:55 PM	TEXAS INSTRUMENTS	

ENGINEER: Robert Blattner	LAYOUT BY: Robert Blattner
SCALE: 1.00	ALTIUM DESIGNER VERSION: 16.0.9.368

Layer	Name	Material	Thickness	Constant	Board Layer Stack
1	Top Overlay				
2	Top Solder	Solder Resist	0.40mil	3.5	
3	Component Side	Copper	1.42mil		
4	Dielectric 1	FR-4	12.00mil	4.2	
5	Ground Plane	Copper	1.42mil		
6	Dielectric 3	FR-4	32.00mil	4.2	
7	Signal Layer 1	Copper	1.42mil		
8	Dielectric 4	FR-4	12.00mil	4.2	
9	Solder Side	Copper	1.42mil		
10	Bottom Solder	Solder Resist	0.40mil	3.5	
11	Bottom Overlay				

DESIGN INFORMATION

MIN. TRACK WIDTH: 8 MIL

MIN. CLEARANCE: 0.2 mm

MIN. VIA PAD SIZE: 24 MIL

MINIMUM ANNULAR RING 0.05mm (2MIL) EXTERNAL

PER IPC-D-275 CLASS 2 LEVEL C

REGISTRATION TOLERANCES: METAL +/- 5 MIL, HOLES +/- 3 MIL

HOLE SIZE TOLERANCE (UNLESS OTHERWISE SPECIFIED): +/- 3 MIL

MATERIAL:

[ ] FR-408 [X] FR-4 High Tg [ ] OTHER _____

THICKNESS: [X] 62 MIL (1.6mm) +/-10% [ ] OTHER _____

TOLERANCE: [X] ANSI IPC-6012 TYPE 3 CLASS 2

[ ] OTHER +/- _____

BOW & TWIST: [X] ANSI IPC-6012 TYPE 3 CLASS 2

[ ] OTHER +/- _____

DRILLING:

REFERENCE: [X] AS SHOWN [X] NC_DRILL FILES

PTH MIN COPPER THICKNESS: [X] 1MIL [ ] OTHER _____

BOARD FINISH:

SILKSCREEN: [X] TOP [X] BOTTOM

SILKSCREEN COLOR: [X] WHITE [ ] OTHER _____

SOLDER RESIST COLOR: [X] GREEN [ ] OTHER _____

[X] MATTE [ ] SEMI-GLOSS

SURFACE FINISH: [X] IMMERSION GOLD (ENIG) [ ] ENEPIG

[ ] IMM. TIN/SILVER OR EQUIV [ ] OTHER _____

ARRAY/PANEL: [ ] CUT AND TRIM PER M1 BOARD OUTLINE

[ ] N.C. ROUTE [X] V. SCORE

CERTIFICATION: MATERIALS AND WORKMANSHIP FOR ALL PCBS TO MEET OR EXCEED THE REQUIREMENTS OF:

[X] ANSI IPC-A-600F CLASS -> [ ] 1 [X] 2 [ ] 3

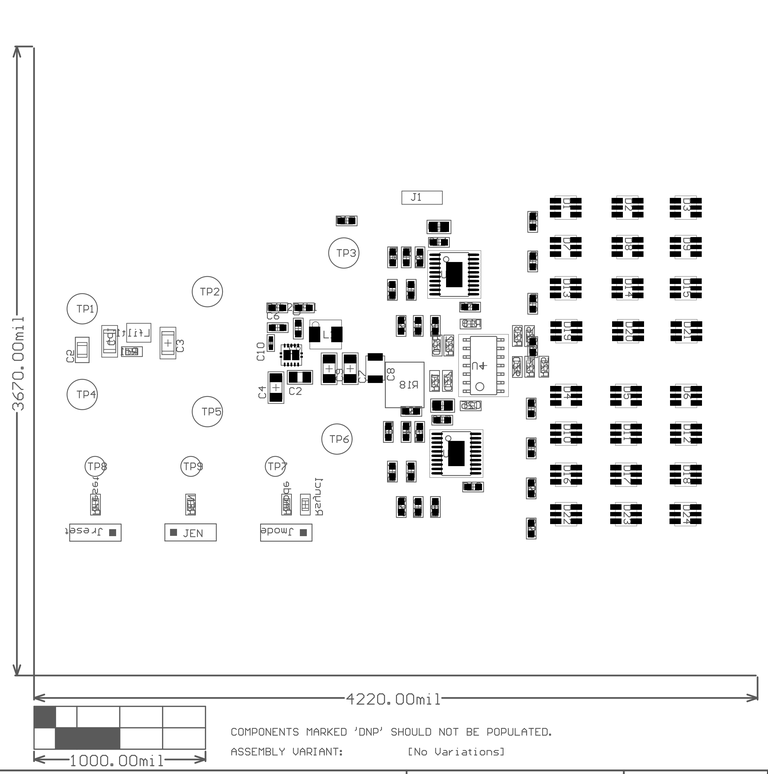
[X] UL 94V-0 [X] RoHS [ ] OTHER PER ORDER

ADDITIONAL REQUIREMENTS:

MICROSECTION: [ ] YES

BARE BOARD ELEC. TEST: [ ] NONE [X] REQUIRED [ ] PER ORDER

MANUFACTURER'S UL: [ ] RAIL [ ] METAL [X] SILK



COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.

ASSEMBLY VARIANT: [No Variations]

TEXAS INSTRUMENTS

PROJECT TITLE: LM5360ONAEVM/O1LAEVM

DESIGNED FOR: Public Release

FILE NAME: TIDA01348.PcbDoc

PCB VIEWED FROM TOP SIDE	BOARD #: TIDA-01348	REV: A	SUN REV: Not In VersionControl
LAYER NAME =	TID #: TIDA-01348		
PLOT NAME = Top Paste Mask Print	GENERATED : 9/26/2016 3:38:00 PM	TEXAS INSTRUMENTS	

ENGINEER: Robert Blattner	LAYOUT BY: Robert Blattner
SCALE: 1.00	ALTIUM DESIGNER VERSION: 16.0.9.368

Layer	Name	Material	Thickness	Constant	Board Layer Stack
1	Top Overlay				
2	Top Solder	Solder Resist	0.40mil	3.5	
3	Component Side	Copper	1.42mil		
4	Dielectric 1	FR-4	12.00mil	4.2	
5	Ground Plane	Copper	1.42mil		
6	Dielectric 3	FR-4	32.00mil	4.2	
7	Signal Layer 1	Copper	1.42mil		
8	Dielectric 4	FR-4	12.00mil	4.2	
9	Solder Side	Copper	1.42mil		
10	Bottom Solder	Solder Resist	0.40mil	3.5	
11	Bottom Overlay				

DESIGN INFORMATION

MIN. TRACK WIDTH: 8 MIL

MIN. CLEARANCE: 0.2 mm

MIN. VIA PAD SIZE: 24 MIL

MINIMUM ANNULAR RING 0.05mm (2MIL) EXTERNAL

PER IPC-D-275 CLASS 2 LEVEL C

REGISTRATION TOLERANCES: METAL +/- 5 MIL, HOLES +/- 3 MIL

HOLE SIZE TOLERANCE (UNLESS OTHERWISE SPECIFIED): +/- 3 MIL

MATERIAL:

[ ] FR-408 [X] FR-4 High Tg [ ] OTHER _____

THICKNESS: [X] 62 MIL (1.6mm) +/-10% [ ] OTHER _____

TOLERANCE: [X] ANSI IPC-6012 TYPE 3 CLASS 2

[ ] OTHER +/- _____

BOW & TWIST: [X] ANSI IPC-6012 TYPE 3 CLASS 2

[ ] OTHER +/- _____

DRILLING:

REFERENCE: [X] AS SHOWN [X] NC_DRILL FILES

PTH MIN COPPER THICKNESS: [X] 1MIL [ ] OTHER _____

BOARD FINISH:

SILKSCREEN: [X] TOP [X] BOTTOM

SILKSCREEN COLOR: [X] WHITE [ ] OTHER _____

SOLDER RESIST COLOR: [X] GREEN [ ] OTHER _____

[X] MATTE [ ] SEMI-GLOSS

SURFACE FINISH: [X] IMMERSION GOLD (ENIG) [ ] ENEPIG

[ ] IMM. TIN/SILVER OR EQUIV [ ] OTHER _____

ARRAY/PANEL: [ ] CUT AND TRIM PER M1 BOARD OUTLINE

[ ] N.C. ROUTE [X] V. SCORE

CERTIFICATION: MATERIALS AND WORKMANSHIP FOR ALL PCBS TO MEET OR EXCEED THE REQUIREMENTS OF:

[X] ANSI IPC-A-600F CLASS -> [ ] 1 [X] 2 [ ] 3

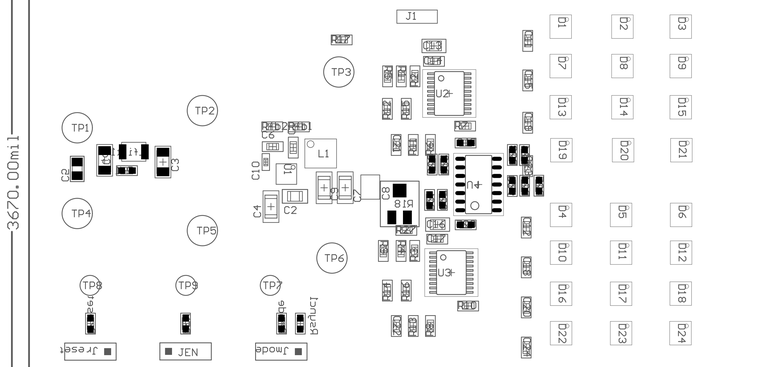
[X] UL 94V-0 [X] RoHS [ ] OTHER PER ORDER

ADDITIONAL REQUIREMENTS:

MICROSECTION: [ ] YES

BARE BOARD ELEC. TEST: [ ] NONE [X] REQUIRED [ ] PER ORDER

MANUFACTURER'S UL: [ ] RAIL [ ] METAL [X] SILK



COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.

ASSEMBLY VARIANT: [No Variations]

TEXAS INSTRUMENTS

PROJECT TITLE: LM53600NAEVM/O1LAEVM

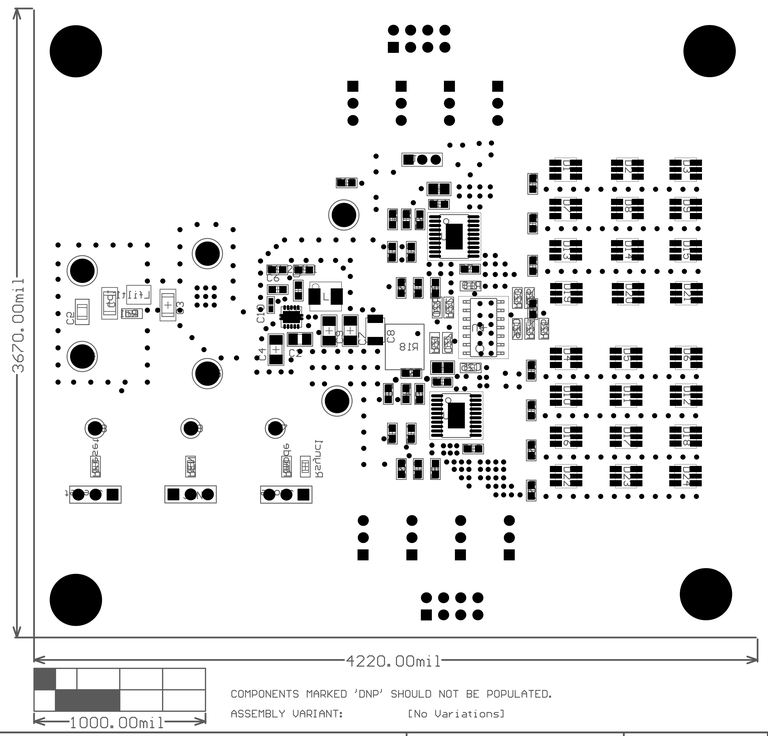
DESIGNED FOR: Public Release

FILE NAME: TIDA01348.PcbDoc

PCB VIEWED FROM TOP SIDE	BOARD #: TIDA-01348	REV: A	SVN REV: Not In VersionControl
LAYER NAME =	TID #: TIDA-01348		
PLOT NAME = Bottom Paste Mask Print	GENERATED : 9/26/2016 3:38:02 PM	TEXAS INSTRUMENTS	

ENGINEER: Robert Blattner	LAYOUT BY: Robert Blattner
SCALE: 1.00	ALTIUM DESIGNER VERSION: 16.0.9.368

Layer	Name	Material	Thickness	Constant	Board Layer Stack
1	Top Overlay				
2	Top Solder	Solder Resist	0.40mil	3.5	
3	Component Side	Copper	1.42mil		
4	Dielectric 1	FR-4	12.00mil	4.2	
5	Ground Plane	Copper	1.42mil		
6	Dielectric 3	FR-4	32.00mil	4.2	
7	Signal Layer 1	Copper	1.42mil		
8	Dielectric 4	FR-4	12.00mil	4.2	
9	Solder Side	Copper	1.42mil		
10	Bottom Solder	Solder Resist	0.40mil	3.5	
11	Bottom Overlay				



COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.
ASSEMBLY VARIANT: [No Variations]

DESIGN INFORMATION

MIN. TRACK WIDTH: 8 MIL
MIN. CLEARANCE: 0.2 mm
MIN. VIA PAD SIZE: 24 MIL
MINIMUM ANNULAR RING 0.05mm (2MIL) EXTERNAL
PER IPC-D-275 CLASS 2 LEVEL C
REGISTRATION TOLERANCES: METAL +/- 5 MIL, HOLES +/- 3 MIL
HOLE SIZE TOLERANCE (UNLESS OTHERWISE SPECIFIED): +/- 3 MIL

MATERIAL:
[ ] FR-408 [X] FR-4 High Tg [ ] OTHER
THICKNESS: [X] 62 MIL (1.6mm) +/-10% [ ] OTHER
TOLERANCE: [X] ANSI IPC-6012 TYPE 3 CLASS 2
[ ] OTHER +/-
BOW & TWIST: [X] ANSI IPC-6012 TYPE 3 CLASS 2
[ ] OTHER +/-
DRILLING:
REFERENCE: [X] AS SHOWN [X] NC_DRILL FILES
PTH MIN COPPER THICKNESS: [X] 1MIL [ ] OTHER
BOARD FINISH:
SILKSCREEN: [X] TOP [X] BOTTOM
SILKSCREEN COLOR: [X] WHITE [ ] OTHER
SOLDER RESIST COLOR: [X] GREEN [ ] OTHER
[X] MATTE [ ] SEMI-GLOSS
SURFACE FINISH: [X] IMMERSION GOLD (ENIG) [ ] ENEPIG
[ ] IMM. TIN/SILVER OR EQUIV [ ] OTHER
ARRAY/PANEL: [ ] CUT AND TRIM PER M1 BOARD OUTLINE
[ ] N.C. ROUTE [X] V. SCORE
CERTIFICATION: MATERIALS AND WORKMANSHIP FOR ALL PCBS TO MEET OR EXCEED THE REQUIREMENTS OF:
[X] ANSI IPC-A-600F CLASS -> [ ] 1 [X] 2 [ ] 3
[X] UL 94V-0 [X] RoHS [ ] OTHER PER ORDER
ADDITIONAL REQUIREMENTS:
MICROSECTION: [ ] YES
BARE BOARD ELEC. TEST: [ ] NONE [X] REQUIRED [ ] PER ORDER
MANUFACTURER'S UL: [ ] RAIL [ ] METAL [X] SILK

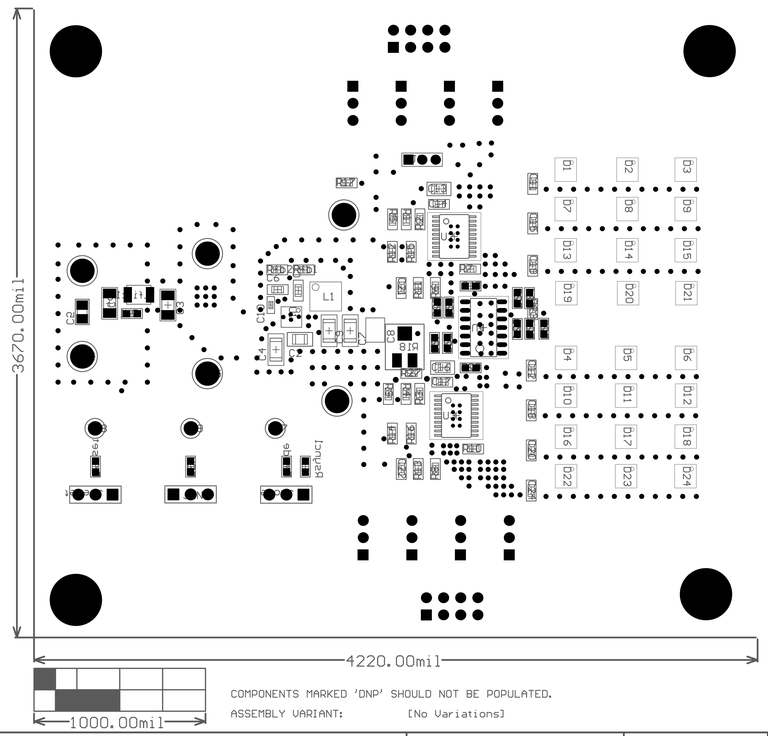
TEXAS INSTRUMENTS

PROJECT TITLE: LM5360ONAEVM/O1LAEVM
DESIGNED FOR: Public Release
FILE NAME: TIDA01348.PcbDoc

PCB VIEWED FROM TOP SIDE	BOARD #: TIDA-01348	REV: A	SVN REV: Not In VersionControl
LAYER NAME =	TID #: TIDA-01348		
PLOT NAME = Top Solder Mask Print	GENERATED : 9/26/2016 3:38:08 PM	TEXAS INSTRUMENTS	

ENGINEER:	LAYOUT BY:
Robert Blattner	Robert Blattner
SCALE: 1.00	ALTIUM DESIGNER VERSION: 16.0.9.368

Layer	Name	Material	Thickness	Constant	Board Layer Stack
1	Top Overlay				
2	Top Solder	Solder Resist	0.40mil	3.5	
3	Component Side	Copper	1.42mil		
4	Dielectric 1	FR-4	12.00mil	4.2	
5	Ground Plane	Copper	1.42mil		
6	Dielectric 3	FR-4	32.00mil	4.2	
7	Signal Layer 1	Copper	1.42mil		
8	Dielectric 4	FR-4	12.00mil	4.2	
9	Solder Side	Copper	1.42mil		
10	Bottom Solder	Solder Resist	0.40mil	3.5	
11	Bottom Overlay				



COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.
ASSEMBLY VARIANT: [No Variations]

DESIGN INFORMATION

MIN. TRACK WIDTH: 8 MIL
MIN. CLEARANCE: 0.2 mm
MIN. VIA PAD SIZE: 24 MIL
MINIMUM ANNULAR RING 0.05mm (2MIL) EXTERNAL
PER IPC-D-275 CLASS 2 LEVEL C
REGISTRATION TOLERANCES: METAL +/- 5 MIL, HOLES +/- 3 MIL
HOLE SIZE TOLERANCE (UNLESS OTHERWISE SPECIFIED): +/- 3 MIL

MATERIAL:
[ ] FR-408 [X] FR-4 High Tg [ ] OTHER
THICKNESS: [X] 62 MIL (1.6mm) +/-10% [ ] OTHER
TOLERANCE: [X] ANSI IPC-6012 TYPE 3 CLASS 2
[ ] OTHER +/-
BOW & TWIST: [X] ANSI IPC-6012 TYPE 3 CLASS 2
[ ] OTHER +/-
DRILLING:
REFERENCE: [X] AS SHOWN [X] NC_DRILL FILES
PTH MIN COPPER THICKNESS: [X] 1MIL [ ] OTHER
BOARD FINISH:
SILKSCREEN: [X] TOP [X] BOTTOM
SILKSCREEN COLOR: [X] WHITE [ ] OTHER
SOLDER RESIST COLOR: [X] GREEN [ ] OTHER
[X] MATTE [ ] SEMI-GLOSS
SURFACE FINISH: [X] IMMERSION GOLD (ENIG) [ ] ENEPIG
[ ] IMM. TIN/SILVER OR EQUIV [ ] OTHER
ARRAY/PANEL: [ ] CUT AND TRIM PER M1 BOARD OUTLINE
[ ] N.C. ROUTE [X] V. SCORE
CERTIFICATION: MATERIALS AND WORKMANSHIP FOR ALL PCBS TO MEET OR EXCEED THE REQUIREMENTS OF:
[X] ANSI IPC-A-600F CLASS -> [ ] 1 [X] 2 [ ] 3
[X] UL 94V-0 [X] RoHS [ ] OTHER PER ORDER
ADDITIONAL REQUIREMENTS:
MICROSECTION: [ ] YES
BARE BOARD ELEC. TEST: [ ] NONE [X] REQUIRED [ ] PER ORDER
MANUFACTURER'S UL: [ ] RAIL [ ] METAL [X] SILK

TEXAS INSTRUMENTS

PROJECT TITLE: LM5360ONAEVM/O1LAEVM
DESIGNED FOR: Public Release
FILE NAME: TIDA01348.PcbDoc

PCB VIEWED FROM TOP SIDE	BOARD #: TIDA-01348	REV: A	SVN REV: Not In VersionControl
LAYER NAME =	TID #: TIDA-01348		
PLOT NAME = Bottom Solder Mask Print	GENERATED : 9/26/2016 3:38:10 PM	TEXAS INSTRUMENTS	

ENGINEER: Robert Blattner	LAYOUT BY: Robert Blattner
SCALE: 1.00	ALTIUM DESIGNER VERSION: 16.0.9.368

Layer	Name	Material	Thickness	Constant	Board Layer Stack
1	Top Overlay				
2	Top Solder	Solder Resist	0.40mil	3.5	
3	Component Side	Copper	1.42mil		
4	Dielectric 1	FR-4	12.00mil	4.2	
5	Ground Plane	Copper	1.42mil		
6	Dielectric 3	FR-4	32.00mil	4.2	
7	Signal Layer 1	Copper	1.42mil		
8	Dielectric 4	FR-4	12.00mil	4.2	
9	Solder Side	Copper	1.42mil		
10	Bottom Solder	Solder Resist	0.40mil	3.5	
11	Bottom Overlay				

DESIGN INFORMATION

MIN. TRACK WIDTH: 8 MIL

MIN. CLEARANCE: 0.2 mm

MIN. VIA PAD SIZE: 24 MIL

MINIMUM ANNULAR RING 0.05mm (2MIL) EXTERNAL

PER IPC-D-275 CLASS 2 LEVEL C

REGISTRATION TOLERANCES: METAL +/- 5 MIL, HOLES +/- 3 MIL

HOLE SIZE TOLERANCE (UNLESS OTHERWISE SPECIFIED): +/- 3 MIL

MATERIAL:

[ ] FR-408 [X] FR-4 High Tg [ ] OTHER _____

THICKNESS: [X] 62 MIL (1.6mm) +/-10% [ ] OTHER _____

TOLERANCE: [X] ANSI IPC-6012 TYPE 3 CLASS 2

[ ] OTHER +/- _____

BOW & TWIST: [X] ANSI IPC-6012 TYPE 3 CLASS 2

[ ] OTHER +/- _____

DRILLING:

REFERENCE: [X] AS SHOWN [X] NC_DRILL FILES

PTH MIN COPPER THICKNESS: [X] 1MIL [ ] OTHER _____

BOARD FINISH:

SILKSCREEN: [X] TOP [X] BOTTOM

SILKSCREEN COLOR: [X] WHITE [ ] OTHER _____

SOLDER RESIST COLOR: [X] GREEN [ ] OTHER _____

[X] MATTE [ ] SEMI-GLOSS

SURFACE FINISH: [X] IMMERSION GOLD (ENIG) [ ] ENEPIG

[ ] IMM. TIN/SILVER OR EQUIV [ ] OTHER _____

ARRAY/PANEL: [ ] CUT AND TRIM PER M1 BOARD OUTLINE

[ ] N.C. ROUTE [X] V. SCORE

CERTIFICATION: MATERIALS AND WORKMANSHIP FOR ALL PCBS TO MEET OR EXCEED THE REQUIREMENTS OF:

[X] ANSI IPC-A-600F CLASS -> [ ] 1 [X] 2 [ ] 3

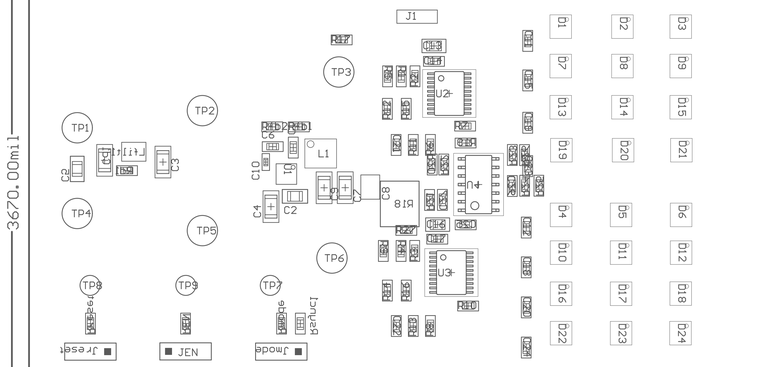
[X] UL 94V-0 [X] RoHS [ ] OTHER PER ORDER

ADDITIONAL REQUIREMENTS:

MICROSECTION: [ ] YES

BARE BOARD ELEC. TEST: [ ] NONE [X] REQUIRED [ ] PER ORDER

MANUFACTURER'S UL: [ ] RAIL [ ] METAL [X] SILK



COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.

ASSEMBLY VARIANT: [No Variations]

TEXAS INSTRUMENTS

PROJECT TITLE: LM53600NAEVM/O1LAEVM

DESIGNED FOR: Public Release

FILE NAME: TIDA01348.PcbDoc

PCB VIEWED FROM TOP SIDE	BOARD #: TIDA-01348	REV: A	SVN REV: Not In VersionControl
LAYER NAME =	TID #: TIDA-01348		
PLOT NAME = Mechanical 1	GENERATED : 9/26/2016 3:38:19 PM	TEXAS INSTRUMENTS	

ENGINEER: Robert Blattner	LAYOUT BY: Robert Blattner
SCALE: 1.00	ALTIUM DESIGNER VERSION: 16.0.9.368

Layer	Name	Material	Thickness	Constant	Board Layer Stack
1	Top Overlay				
2	Top Solder	Solder Resist	0.40mil	3.5	
3	Component Side	Copper	1.42mil		
4	Dielectric 1	FR-4	12.00mil	4.2	
5	Ground Plane	Copper	1.42mil		
6	Dielectric 3	FR-4	32.00mil	4.2	
7	Signal Layer 1	Copper	1.42mil		
8	Dielectric 4	FR-4	12.00mil	4.2	
9	Solder Side	Copper	1.42mil		
10	Bottom Solder	Solder Resist	0.40mil	3.5	
11	Bottom Overlay				

DESIGN INFORMATION

MIN. TRACK WIDTH: 8 MIL

MIN. CLEARANCE: 0.2 mm

MIN. VIA PAD SIZE: 24 MIL

MINIMUM ANNULAR RING 0.05mm (2MIL) EXTERNAL

PER IPC-D-275 CLASS 2 LEVEL C

REGISTRATION TOLERANCES: METAL +/- 5 MIL, HOLES +/- 3 MIL

HOLE SIZE TOLERANCE (UNLESS OTHERWISE SPECIFIED): +/- 3 MIL

MATERIAL:

[ ] FR-408 [X] FR-4 High Tg [ ] OTHER _____

THICKNESS: [X] 62 MIL (1.6mm) +/-10% [ ] OTHER _____

TOLERANCE: [X] ANSI IPC-6012 TYPE 3 CLASS 2

[ ] OTHER +/- _____

BOW & TWIST: [X] ANSI IPC-6012 TYPE 3 CLASS 2

[ ] OTHER +/- _____

DRILLING:

REFERENCE: [X] AS SHOWN [X] NC_DRILL FILES

PTH MIN COPPER THICKNESS: [X] 1MIL [ ] OTHER _____

BOARD FINISH:

SILKSCREEN: [X] TOP [X] BOTTOM

SILKSCREEN COLOR: [X] WHITE [ ] OTHER _____

SOLDER RESIST COLOR: [X] GREEN [ ] OTHER _____

[X] MATTE [ ] SEMI-GLOSS

SURFACE FINISH: [X] IMMERSION GOLD (ENIG) [ ] ENEPIG

[ ] IMM. TIN/SILVER OR EQUIV [ ] OTHER _____

ARRAY/PANEL: [ ] CUT AND TRIM PER M1 BOARD OUTLINE

[ ] N.C. ROUTE [X] V. SCORE

CERTIFICATION: MATERIALS AND WORKMANSHIP FOR ALL PCBS TO MEET OR EXCEED THE REQUIREMENTS OF:

[X] ANSI IPC-A-600F CLASS -> [ ] 1 [X] 2 [ ] 3

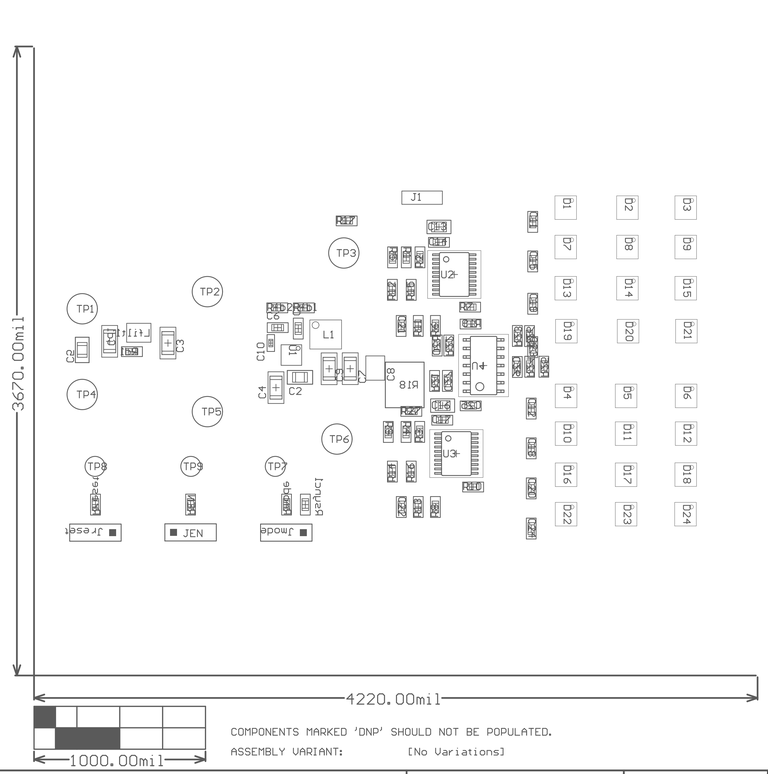
[X] UL 94V-0 [X] RoHS [ ] OTHER PER ORDER

ADDITIONAL REQUIREMENTS:

MICROSECTION: [ ] YES

BARE BOARD ELEC. TEST: [ ] NONE [X] REQUIRED [ ] PER ORDER

MANUFACTURER'S UL: [ ] RAIL [ ] METAL [X] SILK



COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.

ASSEMBLY VARIANT: [No Variations]

TEXAS INSTRUMENTS

PROJECT TITLE: LM53600NAEVM/O1LAEVM

DESIGNED FOR: Public Release

FILE NAME: TIDA01348.PcbDoc

PCB VIEWED FROM TOP SIDE	BOARD #: TIDA-01348	REV: A	SVN REV: Not In VersionControl
LAYER NAME =	TID #: TIDA-01348		
PLOT NAME = Mechanical 2	GENERATED : 9/26/2016 3:38:18 PM	TEXAS INSTRUMENTS	

ENGINEER: Robert Blattner	LAYOUT BY: Robert Blattner
SCALE: 1.00	ALTIUM DESIGNER VERSION: 16.0.9.368

Layer	Name	Material	Thickness	Constant	Board Layer Stack
1	Top Overlay				
2	Top Solder	Solder Resist	0.40mil	3.5	
3	Component Side	Copper	1.42mil		
4	Dielectric 1	FR-4	12.00mil	4.2	
5	Ground Plane	Copper	1.42mil		
6	Dielectric 3	FR-4	32.00mil	4.2	
7	Signal Layer 1	Copper	1.42mil		
8	Dielectric 4	FR-4	12.00mil	4.2	
9	Solder Side	Copper	1.42mil		
10	Bottom Solder	Solder Resist	0.40mil	3.5	
11	Bottom Overlay				

DESIGN INFORMATION

MIN. TRACK WIDTH: 8 MIL

MIN. CLEARANCE: 0.2 mm

MIN. VIA PAD SIZE: 24 MIL

MINIMUM ANNULAR RING 0.05mm (2MIL) EXTERNAL

PER IPC-D-275 CLASS 2 LEVEL C

REGISTRATION TOLERANCES: METAL +/- 5 MIL, HOLES +/- 3 MIL

HOLE SIZE TOLERANCE (UNLESS OTHERWISE SPECIFIED): +/- 3 MIL

MATERIAL:

[ ] FR-408 [X] FR-4 High Tg [ ] OTHER _____

THICKNESS: [X] 62 MIL (1.6mm) +/-10% [ ] OTHER _____

TOLERANCE: [X] ANSI IPC-6012 TYPE 3 CLASS 2

[ ] OTHER +/- _____

BOW & TWIST: [X] ANSI IPC-6012 TYPE 3 CLASS 2

[ ] OTHER +/- _____

DRILLING:

REFERENCE: [X] AS SHOWN [X] NC_DRILL FILES

PTH MIN COPPER THICKNESS: [X] 1MIL [ ] OTHER _____

BOARD FINISH:

SILKSCREEN: [X] TOP [X] BOTTOM

SILKSCREEN COLOR: [X] WHITE [ ] OTHER _____

SOLDER RESIST COLOR: [X] GREEN [ ] OTHER _____

[X] MATTE [ ] SEMI-GLOSS

SURFACE FINISH: [X] IMMERSION GOLD (ENIG) [ ] ENEPIG

[ ] IMM. TIN/SILVER OR EQUIV [ ] OTHER _____

ARRAY/PANEL: [ ] CUT AND TRIM PER M1 BOARD OUTLINE

[ ] N.C. ROUTE [X] V. SCORE

CERTIFICATION: MATERIALS AND WORKMANSHIP FOR ALL PCBS TO MEET OR EXCEED THE REQUIREMENTS OF:

[X] ANSI IPC-A-600F CLASS -> [ ] 1 [X] 2 [ ] 3

[X] UL 94V-0 [X] RoHS [ ] OTHER PER ORDER

ADDITIONAL REQUIREMENTS:

MICROSECTION: [ ] YES

BARE BOARD ELEC. TEST: [ ] NONE [X] REQUIRED [ ] PER ORDER

MANUFACTURER'S UL: [ ] RAIL [ ] METAL [X] SILK

COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.

ASSEMBLY VARIANT: [No Variations]

TEXAS INSTRUMENTS

PROJECT TITLE: LM5360ONAEVM/O1LAEVM

DESIGNED FOR: Public Release

FILE NAME: TIDA01348.PcbDoc

PCB VIEWED FROM TOP SIDE	BOARD #: TIDA-01348	REV: A	SVN REV: Not In VersionControl
LAYER NAME =	TID #: TIDA-01348		
PLOT NAME = Mechanical 3	GENERATED : 9/26/2016 3:38:20 PM	TEXAS INSTRUMENTS	

ENGINEER: Robert Blattner	LAYOUT BY: Robert Blattner
SCALE: 1.00	ALTIUM DESIGNER VERSION: 16.0.9.368

Layer	Name	Material	Thickness	Constant	Board Layer Stack
1	Top Overlay				
2	Top Solder	Solder Resist	0.40mil	3.5	
3	Component Side	Copper	1.42mil		
4	Dielectric 1	FR-4	12.00mil	4.2	
5	Ground Plane	Copper	1.42mil		
6	Dielectric 3	FR-4	32.00mil	4.2	
7	Signal Layer 1	Copper	1.42mil		
8	Dielectric 4	FR-4	12.00mil	4.2	
9	Solder Side	Copper	1.42mil		
10	Bottom Solder	Solder Resist	0.40mil	3.5	
11	Bottom Overlay				

DESIGN INFORMATION

MIN. TRACK WIDTH: 8 MIL

MIN. CLEARANCE: 0.2 mm

MIN. VIA PAD SIZE: 24 MIL

MINIMUM ANNULAR RING 0.05mm (2MIL) EXTERNAL

PER IPC-D-275 CLASS 2 LEVEL C

REGISTRATION TOLERANCES: METAL +/- 5 MIL, HOLES +/- 3 MIL

HOLE SIZE TOLERANCE (UNLESS OTHERWISE SPECIFIED): +/- 3 MIL

MATERIAL:

[ ] FR-408 [X] FR-4 High Tg [ ] OTHER _____

THICKNESS: [X] 62 MIL (1.6mm) +/-10% [ ] OTHER _____

TOLERANCE: [X] ANSI IPC-6012 TYPE 3 CLASS 2

[ ] OTHER +/- _____

BOW & TWIST: [X] ANSI IPC-6012 TYPE 3 CLASS 2

[ ] OTHER +/- _____

DRILLING:

REFERENCE: [X] AS SHOWN [X] NC_DRILL FILES

PTH MIN COPPER THICKNESS: [X] 1MIL [ ] OTHER _____

BOARD FINISH:

SILKSCREEN: [X] TOP [X] BOTTOM

SILKSCREEN COLOR: [X] WHITE [ ] OTHER _____

SOLDER RESIST COLOR: [X] GREEN [ ] OTHER _____

[X] MATTE [ ] SEMI-GLOSS

SURFACE FINISH: [X] IMMERSION GOLD (ENIG) [ ] ENEPIG

[ ] IMM. TIN/SILVER OR EQUIV [ ] OTHER _____

ARRAY/PANEL: [ ] CUT AND TRIM PER M1 BOARD OUTLINE

[ ] N.C. ROUTE [X] V. SCORE

CERTIFICATION: MATERIALS AND WORKMANSHIP FOR ALL PCBS TO MEET OR EXCEED THE REQUIREMENTS OF:

[X] ANSI IPC-A-600F CLASS -> [ ] 1 [X] 2 [ ] 3

[X] UL 94V-0 [X] RoHS [ ] OTHER PER ORDER

ADDITIONAL REQUIREMENTS:

MICROSECTION: [ ] YES

BARE BOARD ELEC. TEST: [ ] NONE [X] REQUIRED [ ] PER ORDER

MANUFACTURER'S UL: [ ] RAIL [ ] METAL [X] SILK

COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.

ASSEMBLY VARIANT: [No Variations]

TEXAS INSTRUMENTS

PROJECT TITLE: LM53600NAEVM/O1LAEVM

DESIGNED FOR: Public Release

FILE NAME: TIDA01348.PcbDoc

PCB VIEWED FROM TOP SIDE	BOARD #: TIDA-01348	REV: A	SVN REV: Not In VersionControl
LAYER NAME =	TID #: TIDA-01348		
PLOT NAME = Mechanical 4	GENERATED : 9/26/2016 3:38:29 PM	TEXAS INSTRUMENTS	

ENGINEER: Robert Blattner	LAYOUT BY: Robert Blattner
SCALE: 1.00	ALTIUM DESIGNER VERSION: 16.0.9.368

Layer	Name	Material	Thickness	Constant	Board Layer Stack
1	Top Overlay				
2	Top Solder	Solder Resist	0.40mil	3.5	
3	Component Side	Copper	1.42mil		
4	Dielectric 1	FR-4	12.00mil	4.2	
5	Ground Plane	Copper	1.42mil		
6	Dielectric 3	FR-4	32.00mil	4.2	
7	Signal Layer 1	Copper	1.42mil		
8	Dielectric 4	FR-4	12.00mil	4.2	
9	Solder Side	Copper	1.42mil		
10	Bottom Solder	Solder Resist	0.40mil	3.5	
11	Bottom Overlay				

DESIGN INFORMATION

MIN. TRACK WIDTH: 8 MIL

MIN. CLEARANCE: 0.2 mm

MIN. VIA PAD SIZE: 24 MIL

MINIMUM ANNULAR RING 0.05mm (2MIL) EXTERNAL

PER IPC-D-275 CLASS 2 LEVEL C

REGISTRATION TOLERANCES: METAL +/- 5 MIL, HOLES +/- 3 MIL

HOLE SIZE TOLERANCE (UNLESS OTHERWISE SPECIFIED): +/- 3 MIL

MATERIAL:

[ ] FR-408 [X] FR-4 High Tg [ ] OTHER _____

THICKNESS: [X] 62 MIL (1.6mm) +/-10% [ ] OTHER _____

TOLERANCE: [X] ANSI IPC-6012 TYPE 3 CLASS 2

[ ] OTHER +/- _____

BOW & TWIST: [X] ANSI IPC-6012 TYPE 3 CLASS 2

[ ] OTHER +/- _____

DRILLING:

REFERENCE: [X] AS SHOWN [X] NC_DRILL FILES

PTH MIN COPPER THICKNESS: [X] 1MIL [ ] OTHER _____

BOARD FINISH:

SILKSCREEN: [X] TOP [X] BOTTOM

SILKSCREEN COLOR: [X] WHITE [ ] OTHER _____

SOLDER RESIST COLOR: [X] GREEN [ ] OTHER _____

[X] MATTE [ ] SEMI-GLOSS

SURFACE FINISH: [X] IMMERSION GOLD (ENIG) [ ] ENEPIG

[ ] IMM. TIN/SILVER OR EQUIV [ ] OTHER _____

ARRAY/PANEL: [ ] CUT AND TRIM PER M1 BOARD OUTLINE

[ ] N.C. ROUTE [X] V. SCORE

CERTIFICATION: MATERIALS AND WORKMANSHIP FOR ALL PCBS TO MEET OR EXCEED THE REQUIREMENTS OF:

[X] ANSI IPC-A-600F CLASS -> [ ] 1 [X] 2 [ ] 3

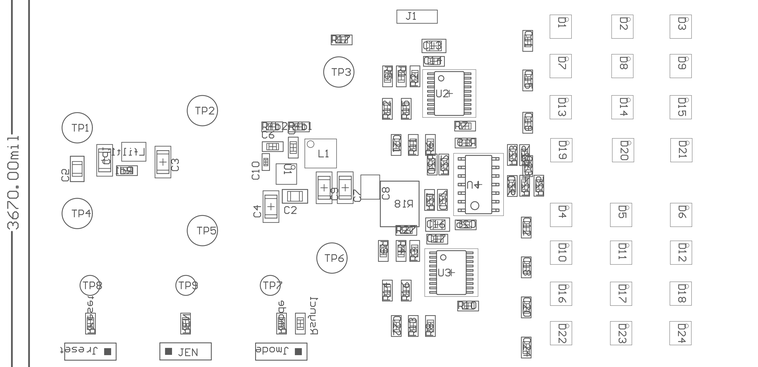
[X] UL 94V-0 [X] RoHS [ ] OTHER PER ORDER

ADDITIONAL REQUIREMENTS:

MICROSECTION: [ ] YES

BARE BOARD ELEC. TEST: [ ] NONE [X] REQUIRED [ ] PER ORDER

MANUFACTURER'S UL: [ ] RAIL [ ] METAL [X] SILK



COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.

ASSEMBLY VARIANT: [No Variations]

TEXAS INSTRUMENTS

PROJECT TITLE: LM5360ONAEVM/O1LAEVM

DESIGNED FOR: Public Release

FILE NAME: TIDA01348.PcbDoc

PCB VIEWED FROM TOP SIDE	BOARD #: TIDA-01348	REV: A	SVN REV: Not In VersionControl
LAYER NAME =	TID #: TIDA-01348		
PLOT NAME = Mechanical 5	GENERATED : 9/26/2016 3:38:20 PM	TEXAS INSTRUMENTS	

ENGINEER: Robert Blattner	LAYOUT BY: Robert Blattner
SCALE: 1.00	ALTIUM DESIGNER VERSION: 16.0.9.368

Layer	Name	Material	Thickness	Constant	Board Layer Stack
1	Top Overlay				
2	Top Solder	Solder Resist	0.40mil	3.5	
3	Component Side	Copper	1.42mil		
4	Dielectric 1	FR-4	12.00mil	4.2	
5	Ground Plane	Copper	1.42mil		
6	Dielectric 3	FR-4	32.00mil	4.2	
7	Signal Layer 1	Copper	1.42mil		
8	Dielectric 4	FR-4	12.00mil	4.2	
9	Solder Side	Copper	1.42mil		
10	Bottom Solder	Solder Resist	0.40mil	3.5	
11	Bottom Overlay				

DESIGN INFORMATION

MIN. TRACK WIDTH: 8 MIL

MIN. CLEARANCE: 0.2 mm

MIN. VIA PAD SIZE: 24 MIL

MINIMUM ANNULAR RING 0.05mm (2MIL) EXTERNAL

PER IPC-D-275 CLASS 2 LEVEL C

REGISTRATION TOLERANCES: METAL +/- 5 MIL, HOLES +/- 3 MIL

HOLE SIZE TOLERANCE (UNLESS OTHERWISE SPECIFIED): +/- 3 MIL

MATERIAL:

[ ] FR-408 [X] FR-4 High Tg [ ] OTHER _____

THICKNESS: [X] 62 MIL (1.6mm) +/-10% [ ] OTHER _____

TOLERANCE: [X] ANSI IPC-6012 TYPE 3 CLASS 2

[ ] OTHER +/- _____

BOW & TWIST: [X] ANSI IPC-6012 TYPE 3 CLASS 2

[ ] OTHER +/- _____

DRILLING:

REFERENCE: [X] AS SHOWN [X] NC_DRILL FILES

PTH MIN COPPER THICKNESS: [X] 1MIL [ ] OTHER _____

BOARD FINISH:

SILKSCREEN: [X] TOP [X] BOTTOM

SILKSCREEN COLOR: [X] WHITE [ ] OTHER _____

SOLDER RESIST COLOR: [X] GREEN [ ] OTHER _____

[X] MATTE [ ] SEMI-GLOSS

SURFACE FINISH: [X] IMMERSION GOLD (ENIG) [ ] ENEPIG

[ ] IMM. TIN/SILVER OR EQUIV [ ] OTHER _____

ARRAY/PANEL: [ ] CUT AND TRIM PER M1 BOARD OUTLINE

[ ] N.C. ROUTE [X] V. SCORE

CERTIFICATION: MATERIALS AND WORKMANSHIP FOR ALL PCBS TO MEET OR EXCEED THE REQUIREMENTS OF:

[X] ANSI IPC-A-600F CLASS -> [ ] 1 [X] 2 [ ] 3

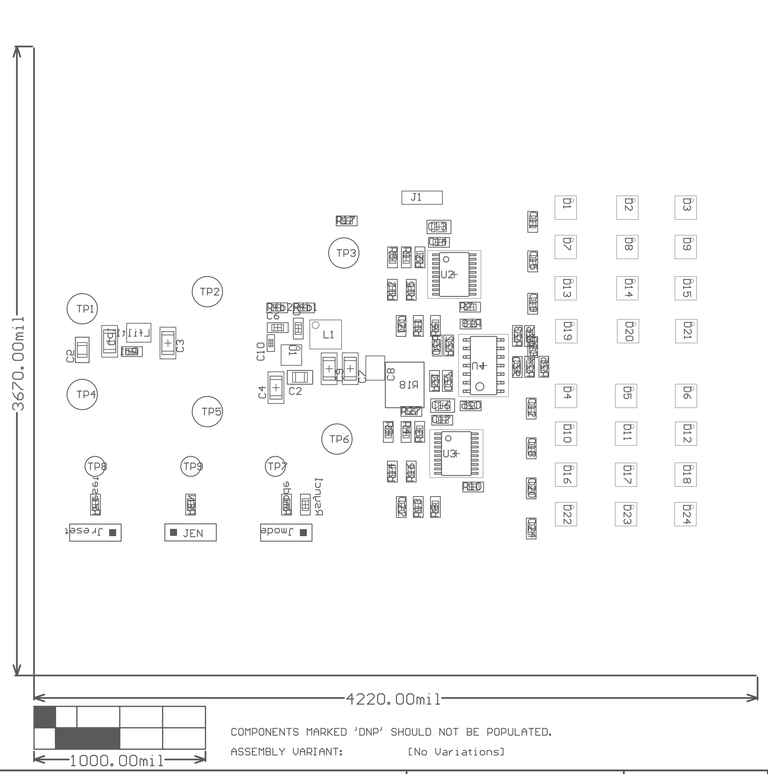
[X] UL 94V-0 [X] RoHS [ ] OTHER PER ORDER

ADDITIONAL REQUIREMENTS:

MICROSECTION: [ ] YES

BARE BOARD ELEC. TEST: [ ] NONE [X] REQUIRED [ ] PER ORDER

MANUFACTURER'S UL: [ ] RAIL [ ] METAL [X] SILK



COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.

ASSEMBLY VARIANT: [No Variations]

TEXAS INSTRUMENTS

PROJECT TITLE: LM53600NAEVM/O1LAEVM

DESIGNED FOR: Public Release

FILE NAME: TIDA01348.PcbDoc

PCB VIEWED FROM TOP SIDE	BOARD #: TIDA-01348	REV: A	SVN REV: Not In VersionControl
LAYER NAME =	TID #: TIDA-01348		
PLOT NAME = Mechanical 6	GENERATED : 9/26/2016 3:38:30 PM		TEXAS INSTRUMENTS

ENGINEER: Robert Blattner	LAYOUT BY: Robert Blattner
SCALE: 1.00	ALTIUM DESIGNER VERSION: 16.0.9.368

Layer	Name	Material	Thickness	Constant	Board Layer Stack
1	Top Overlay				
2	Top Solder	Solder Resist	0.40mil	3.5	
3	Component Side	Copper	1.42mil		
4	Dielectric 1	FR-4	12.00mil	4.2	
5	Ground Plane	Copper	1.42mil		
6	Dielectric 3	FR-4	32.00mil	4.2	
7	Signal Layer 1	Copper	1.42mil		
8	Dielectric 4	FR-4	12.00mil	4.2	
9	Solder Side	Copper	1.42mil		
10	Bottom Solder	Solder Resist	0.40mil	3.5	
11	Bottom Overlay				

DESIGN INFORMATION

MIN. TRACK WIDTH: 8 MIL

MIN. CLEARANCE: 0.2 mm

MIN. VIA PAD SIZE: 24 MIL

MINIMUM ANNULAR RING 0.05mm (2MIL) EXTERNAL

PER IPC-D-275 CLASS 2 LEVEL C

REGISTRATION TOLERANCES: METAL +/- 5 MIL, HOLES +/- 3 MIL

HOLE SIZE TOLERANCE (UNLESS OTHERWISE SPECIFIED): +/- 3 MIL

MATERIAL:

[ ] FR-408 [X] FR-4 High Tg [ ] OTHER _____

THICKNESS: [X] 62 MIL (1.6mm) +/-10% [ ] OTHER _____

TOLERANCE: [X] ANSI IPC-6012 TYPE 3 CLASS 2

[ ] OTHER +/- _____

BOW & TWIST: [X] ANSI IPC-6012 TYPE 3 CLASS 2

[ ] OTHER +/- _____

DRILLING:

REFERENCE: [X] AS SHOWN [X] NC_DRILL FILES

PTH MIN COPPER THICKNESS: [X] 1MIL [ ] OTHER _____

BOARD FINISH:

SILKSCREEN: [X] TOP [X] BOTTOM

SILKSCREEN COLOR: [X] WHITE [ ] OTHER _____

SOLDER RESIST COLOR: [X] GREEN [ ] OTHER _____

[X] MATTE [ ] SEMI-GLOSS

SURFACE FINISH: [X] IMMERSION GOLD (ENIG) [ ] ENEPIG

[ ] IMM. TIN/SILVER OR EQUIV [ ] OTHER _____

ARRAY/PANEL: [ ] CUT AND TRIM PER M1 BOARD OUTLINE

[ ] N.C. ROUTE [X] V. SCORE

CERTIFICATION: MATERIALS AND WORKMANSHIP FOR ALL PCBS TO MEET OR EXCEED THE REQUIREMENTS OF:

[X] ANSI IPC-A-600F CLASS -> [ ] 1 [X] 2 [ ] 3

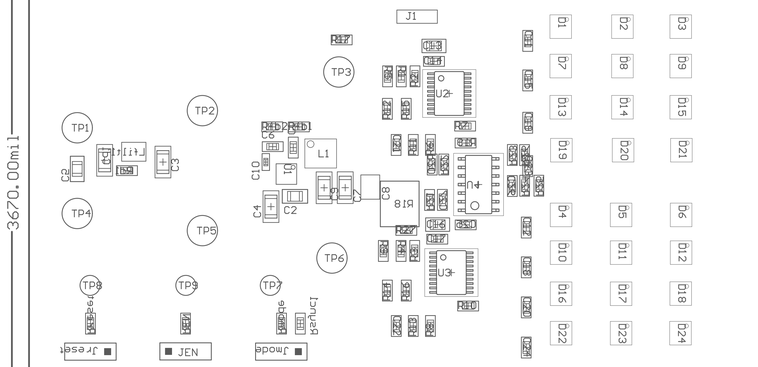
[X] UL 94V-0 [X] RoHS [ ] OTHER PER ORDER

ADDITIONAL REQUIREMENTS:

MICROSECTION: [ ] YES

BARE BOARD ELEC. TEST: [ ] NONE [X] REQUIRED [ ] PER ORDER

MANUFACTURER'S UL: [ ] RAIL [ ] METAL [X] SILK



COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.

ASSEMBLY VARIANT: [No Variations]

TEXAS INSTRUMENTS

PROJECT TITLE: LM53600NAEVM/O1LAEVM

DESIGNED FOR: Public Release

FILE NAME: TIDA01348.PcbDoc

PCB VIEWED FROM TOP SIDE	BOARD #: TIDA-01348	REV: A	SVN REV: Not In VersionControl
LAYER NAME =	TID #: TIDA-01348		
PLOT NAME = Mechanical 9	GENERATED : 9/26/2016 3:38:35 PM	TEXAS INSTRUMENTS	

ENGINEER: Robert Blattner	LAYOUT BY: Robert Blattner
SCALE: 1.00	ALTIUM DESIGNER VERSION: 16.0.9.368

Layer	Name	Material	Thickness	Constant	Board Layer Stack
1	Top Overlay				
2	Top Solder	Solder Resist	0.40mil	3.5	
3	Component Side	Copper	1.42mil		
4	Dielectric 1	FR-4	12.00mil	4.2	
5	Ground Plane	Copper	1.42mil		
6	Dielectric 3	FR-4	32.00mil	4.2	
7	Signal Layer 1	Copper	1.42mil		
8	Dielectric 4	FR-4	12.00mil	4.2	
9	Solder Side	Copper	1.42mil		
10	Bottom Solder	Solder Resist	0.40mil	3.5	
11	Bottom Overlay				

DESIGN INFORMATION

MIN. TRACK WIDTH: 8 MIL

MIN. CLEARANCE: 0.2 mm

MIN. VIA PAD SIZE: 24 MIL

MINIMUM ANNULAR RING 0.05mm (2MIL) EXTERNAL

PER IPC-D-275 CLASS 2 LEVEL C

REGISTRATION TOLERANCES: METAL +/- 5 MIL, HOLES +/- 3 MIL

HOLE SIZE TOLERANCE (UNLESS OTHERWISE SPECIFIED): +/- 3 MIL

MATERIAL:

[ ] FR-408 [X] FR-4 High Tg [ ] OTHER

THICKNESS: [X] 62 MIL (1.6mm) +/-10% [ ] OTHER

TOLERANCE: [X] ANSI IPC-6012 TYPE 3 CLASS 2

[ ] OTHER +/-

BOW & TWIST: [X] ANSI IPC-6012 TYPE 3 CLASS 2

[ ] OTHER +/-

DRILLING:

REFERENCE: [X] AS SHOWN [X] NC_DRILL FILES

PTH MIN COPPER THICKNESS: [X] 1MIL [ ] OTHER

BOARD FINISH:

SILKSCREEN: [X] TOP [X] BOTTOM

SILKSCREEN COLOR: [X] WHITE [ ] OTHER

SOLDER RESIST COLOR: [X] GREEN [ ] OTHER

[X] MATTE [ ] SEMI-GLOSS

SURFACE FINISH: [X] IMMERSION GOLD (ENIG) [ ] ENEPIG

[ ] IMM. TIN/SILVER OR EQUIV [ ] OTHER

ARRAY/PANEL: [ ] CUT AND TRIM PER M1 BOARD OUTLINE

[ ] N.C. ROUTE [X] V. SCORE

CERTIFICATION: MATERIALS AND WORKMANSHIP FOR ALL PCBS TO MEET OR EXCEED THE REQUIREMENTS OF:

[X] ANSI IPC-A-600F CLASS -> [ ] 1 [X] 2 [ ] 3

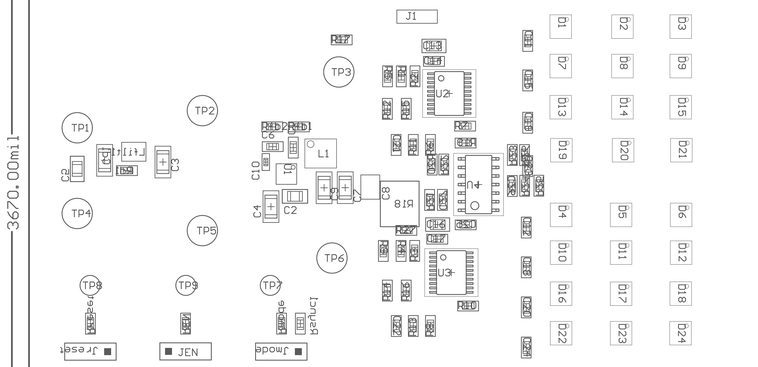
[X] UL 94V-0 [X] RoHS [ ] OTHER PER ORDER

ADDITIONAL REQUIREMENTS:

MICROSECTION: [ ] YES

BARE BOARD ELEC. TEST: [ ] NONE [X] REQUIRED [ ] PER ORDER

MANUFACTURER'S UL: [ ] RAIL [ ] METAL [X] SILK



COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.

ASSEMBLY VARIANT: [No Variations]

TEXAS INSTRUMENTS

PROJECT TITLE: LM53600NAEVM/O1LAEVM

DESIGNED FOR: Public Release

FILE NAME: TIDA01348.PcbDoc

PCB VIEWED FROM TOP SIDE	BOARD #: TIDA-01348	REV: A	SVN REV: Not In VersionControl
LAYER NAME =	TID #: TIDA-01348		
PLOT NAME = Mechanical 10	GENERATED : 9/26/2016 3:38:38 PM	TEXAS INSTRUMENTS	

ENGINEER: Robert Blattner	LAYOUT BY: Robert Blattner
SCALE: 1.00	ALTIUM DESIGNER VERSION: 16.0.9.368

Layer	Name	Material	Thickness	Constant	Board Layer Stack
1	Top Overlay				
2	Top Solder	Solder Resist	0.40mil	3.5	
3	Component Side	Copper	1.42mil		
4	Dielectric 1	FR-4	12.00mil	4.2	
5	Ground Plane	Copper	1.42mil		
6	Dielectric 3	FR-4	32.00mil	4.2	
7	Signal Layer 1	Copper	1.42mil		
8	Dielectric 4	FR-4	12.00mil	4.2	
9	Solder Side	Copper	1.42mil		
10	Bottom Solder	Solder Resist	0.40mil	3.5	
11	Bottom Overlay				

DESIGN INFORMATION

MIN. TRACK WIDTH: 8 MIL

MIN. CLEARANCE: 0.2 mm

MIN. VIA PAD SIZE: 24 MIL

MINIMUM ANNULAR RING 0.05mm (2MIL) EXTERNAL

PER IPC-D-275 CLASS 2 LEVEL C

REGISTRATION TOLERANCES: METAL +/- 5 MIL, HOLES +/- 3 MIL

HOLE SIZE TOLERANCE (UNLESS OTHERWISE SPECIFIED): +/- 3 MIL

MATERIAL:

[ ] FR-408 [X] FR-4 High Tg [ ] OTHER

THICKNESS: [X] 62 MIL (1.6mm) +/-10% [ ] OTHER

TOLERANCE: [X] ANSI IPC-6012 TYPE 3 CLASS 2

[ ] OTHER +/-

BOW & TWIST: [X] ANSI IPC-6012 TYPE 3 CLASS 2

[ ] OTHER +/-

DRILLING:

REFERENCE: [X] AS SHOWN [X] NC_DRILL FILES

PTH MIN COPPER THICKNESS: [X] 1MIL [ ] OTHER

BOARD FINISH:

SILKSCREEN: [X] TOP [X] BOTTOM

SILKSCREEN COLOR: [X] WHITE [ ] OTHER

SOLDER RESIST COLOR: [X] GREEN [ ] OTHER

[X] MATTE [ ] SEMI-GLOSS

SURFACE FINISH: [X] IMMERSION GOLD (ENIG) [ ] ENEPIG

[ ] IMM. TIN/SILVER OR EQUIV [ ] OTHER

ARRAY/PANEL: [ ] CUT AND TRIM PER M1 BOARD OUTLINE

[ ] N.C. ROUTE [X] V. SCORE

CERTIFICATION: MATERIALS AND WORKMANSHIP FOR ALL PCBS TO MEET OR EXCEED THE REQUIREMENTS OF:

[X] ANSI IPC-A-600F CLASS -> [ ] 1 [X] 2 [ ] 3

[X] UL 94V-0 [X] RoHS [ ] OTHER PER ORDER

ADDITIONAL REQUIREMENTS:

MICROSECTION: [ ] YES

BARE BOARD ELEC. TEST: [ ] NONE [X] REQUIRED [ ] PER ORDER

MANUFACTURER'S UL: [ ] RAIL [ ] METAL [X] SILK

COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.

ASSEMBLY VARIANT: [No Variations]

TEXAS INSTRUMENTS

PROJECT TITLE: LM53600NAEVM/01LAEVM

DESIGNED FOR: Public Release

FILE NAME: TIDA01348.PcbDoc

PCB VIEWED FROM TOP SIDE	BOARD #: TIDA-01348	REV: A	SVN REV: Not In VersionControl
LAYER NAME =	TID #: TIDA-01348		
PLOT NAME = Mechanical 11	GENERATED : 9/26/2016 3:38:48 PM	TEXAS INSTRUMENTS	

ENGINEER: Robert Blattner	LAYOUT BY: Robert Blattner
SCALE: 1.00	ALTIUM DESIGNER VERSION: 16.0.9.368

Layer	Name	Material	Thickness	Constant	Board Layer Stack
1	Top Overlay				
2	Top Solder	Solder Resist	0.40mil	3.5	
3	Component Side	Copper	1.42mil		
4	Dielectric 1	FR-4	12.00mil	4.2	
5	Ground Plane	Copper	1.42mil		
6	Dielectric 3	FR-4	32.00mil	4.2	
7	Signal Layer 1	Copper	1.42mil		
8	Dielectric 4	FR-4	12.00mil	4.2	
9	Solder Side	Copper	1.42mil		
10	Bottom Solder	Solder Resist	0.40mil	3.5	
11	Bottom Overlay				

DESIGN INFORMATION

MIN. TRACK WIDTH: 8 MIL

MIN. CLEARANCE: 0.2 mm

MIN. VIA PAD SIZE: 24 MIL

MINIMUM ANNULAR RING 0.05mm (2MIL) EXTERNAL

PER IPC-D-275 CLASS 2 LEVEL C

REGISTRATION TOLERANCES: METAL +/- 5 MIL, HOLES +/- 3 MIL

HOLE SIZE TOLERANCE (UNLESS OTHERWISE SPECIFIED): +/- 3 MIL

MATERIAL:

[ ] FR-408 [X] FR-4 High Tg [ ] OTHER _____

THICKNESS: [X] 62 MIL (1.6mm) +/-10% [ ] OTHER _____

TOLERANCE: [X] ANSI IPC-6012 TYPE 3 CLASS 2

[ ] OTHER +/- _____

BOW & TWIST: [X] ANSI IPC-6012 TYPE 3 CLASS 2

[ ] OTHER +/- _____

DRILLING:

REFERENCE: [X] AS SHOWN [X] NC_DRILL FILES

PTH MIN COPPER THICKNESS: [X] 1MIL [ ] OTHER _____

BOARD FINISH:

SILKSCREEN: [X] TOP [X] BOTTOM

SILKSCREEN COLOR: [X] WHITE [ ] OTHER _____

SOLDER RESIST COLOR: [X] GREEN [ ] OTHER _____

[X] MATTE [ ] SEMI-GLOSS

SURFACE FINISH: [X] IMMERSION GOLD (ENIG) [ ] ENEPIG

[ ] IMM. TIN/SILVER OR EQUIV [ ] OTHER _____

ARRAY/PANEL: [ ] CUT AND TRIM PER M1 BOARD OUTLINE

[ ] N.C. ROUTE [X] V. SCORE

CERTIFICATION: MATERIALS AND WORKMANSHIP FOR ALL PCBS TO MEET OR EXCEED THE REQUIREMENTS OF:

[X] ANSI IPC-A-600F CLASS -> [ ] 1 [X] 2 [ ] 3

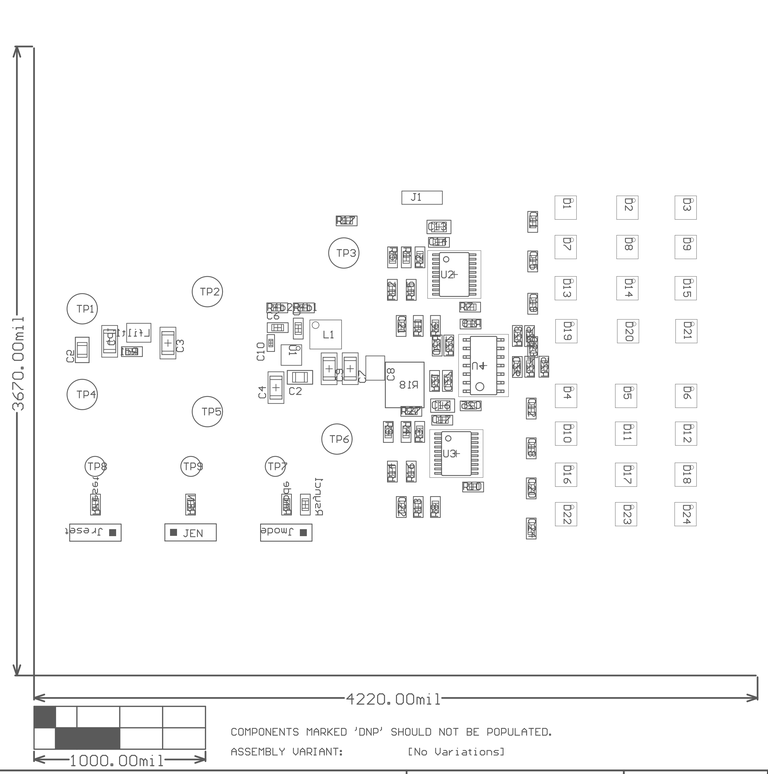
[X] UL 94V-0 [X] RoHS [ ] OTHER PER ORDER

ADDITIONAL REQUIREMENTS:

MICROSECTION: [ ] YES

BARE BOARD ELEC. TEST: [ ] NONE [X] REQUIRED [ ] PER ORDER

MANUFACTURER'S UL: [ ] RAIL [ ] METAL [X] SILK



COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.

ASSEMBLY VARIANT: [No Variations]

TEXAS INSTRUMENTS

PROJECT TITLE: LM53600NAEVM/O1LAEVM

DESIGNED FOR: Public Release

FILE NAME: TIDA01348.PcbDoc

PCB VIEWED FROM TOP SIDE	BOARD #: TIDA-01348	REV: A	SVN REV: Not In VersionControl
LAYER NAME =	TID #: TIDA-01348		
PLOT NAME = Mechanical 12	GENERATED : 9/26/2016 3:38:45 PM	TEXAS INSTRUMENTS	

ENGINEER: Robert Blattner	LAYOUT BY: Robert Blattner
SCALE: 1.00	ALTIUM DESIGNER VERSION: 16.0.9.368

Layer	Name	Material	Thickness	Constant	Board Layer Stack
1	Top Overlay				
2	Top Solder	Solder Resist	0.40mil	3.5	
3	Component Side	Copper	1.42mil		
4	Dielectric 1	FR-4	12.00mil	4.2	
5	Ground Plane	Copper	1.42mil		
6	Dielectric 3	FR-4	32.00mil	4.2	
7	Signal Layer 1	Copper	1.42mil		
8	Dielectric 4	FR-4	12.00mil	4.2	
9	Solder Side	Copper	1.42mil		
10	Bottom Solder	Solder Resist	0.40mil	3.5	
11	Bottom Overlay				

DESIGN INFORMATION

MIN. TRACK WIDTH: 8 MIL

MIN. CLEARANCE: 0.2 mm

MIN. VIA PAD SIZE: 24 MIL

MINIMUM ANNULAR RING 0.05mm (2MIL) EXTERNAL

PER IPC-D-275 CLASS 2 LEVEL C

REGISTRATION TOLERANCES: METAL +/- 5 MIL, HOLES +/- 3 MIL

HOLE SIZE TOLERANCE (UNLESS OTHERWISE SPECIFIED): +/- 3 MIL

MATERIAL:

[ ] FR-408 [X] FR-4 High Tg [ ] OTHER _____

THICKNESS: [X] 62 MIL (1.6mm) +/-10% [ ] OTHER _____

TOLERANCE: [X] ANSI IPC-6012 TYPE 3 CLASS 2

[ ] OTHER +/- _____

BOW & TWIST: [X] ANSI IPC-6012 TYPE 3 CLASS 2

[ ] OTHER +/- _____

DRILLING:

REFERENCE: [X] AS SHOWN [X] NC_DRILL FILES

PTH MIN COPPER THICKNESS: [X] 1MIL [ ] OTHER _____

BOARD FINISH:

SILKSCREEN: [X] TOP [X] BOTTOM

SILKSCREEN COLOR: [X] WHITE [ ] OTHER _____

SOLDER RESIST COLOR: [X] GREEN [ ] OTHER _____

[X] MATTE [ ] SEMI-GLOSS

SURFACE FINISH: [X] IMMERSION GOLD (ENIG) [ ] ENEPIG

[ ] IMM. TIN/SILVER OR EQUIV [ ] OTHER _____

ARRAY/PANEL: [ ] CUT AND TRIM PER M1 BOARD OUTLINE

[ ] N.C. ROUTE [X] V. SCORE

CERTIFICATION: MATERIALS AND WORKMANSHIP FOR ALL PCBS TO MEET OR EXCEED THE REQUIREMENTS OF:

[X] ANSI IPC-A-600F CLASS -> [ ] 1 [X] 2 [ ] 3

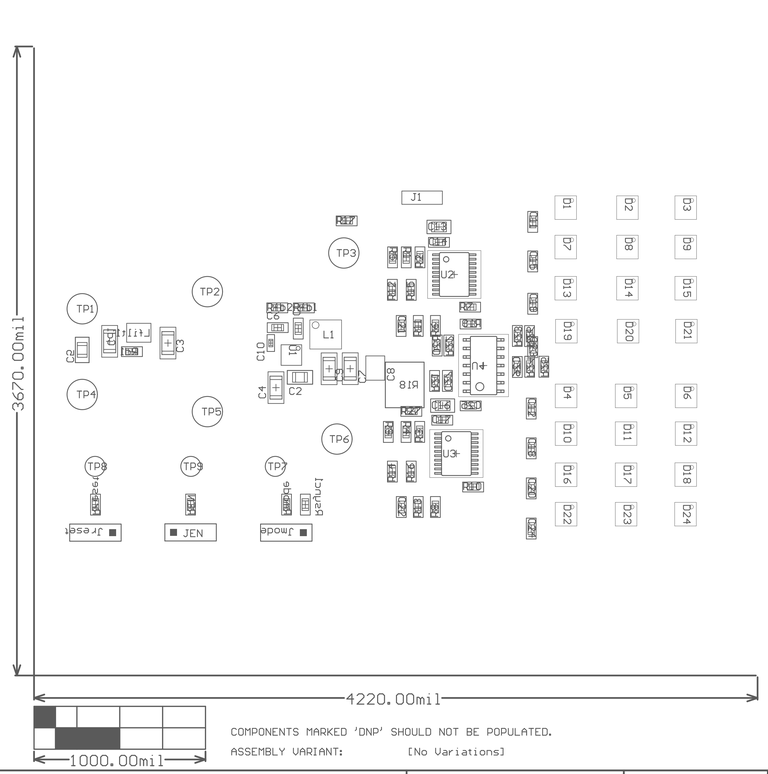
[X] UL 94V-0 [X] RoHS [ ] OTHER PER ORDER

ADDITIONAL REQUIREMENTS:

MICROSECTION: [ ] YES

BARE BOARD ELEC. TEST: [ ] NONE [X] REQUIRED [ ] PER ORDER

MANUFACTURER'S UL: [ ] RAIL [ ] METAL [X] SILK



COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.

ASSEMBLY VARIANT: [No Variations]

TEXAS INSTRUMENTS

PROJECT TITLE:	LM53600NAEVM/O1LAEVM			
DESIGNED FOR:	Public Release			
FILE NAME:	TIDA01348.PcbDoc			
PCB VIEWED FROM TOP SIDE	BOARD #: TIDA-01348	REV: A	SVN REV: Not In VersionControl	
LAYER NAME =	TID #: TIDA-01348			
PLOT NAME = Mechanical 13	GENERATED : 9/26/2016 3:38:48 PM		TEXAS INSTRUMENTS	

ENGINEER: Robert Blattner	LAYOUT BY: Robert Blattner
SCALE: 1.00	ALTIUM DESIGNER VERSION: 16.0.9.368

Layer	Name	Material	Thickness	Constant	Board Layer Stack
1	Top Overlay				
2	Top Solder	Solder Resist	0.40mil	3.5	
3	Component Side	Copper	1.42mil		
4	Dielectric 1	FR-4	12.00mil	4.2	
5	Ground Plane	Copper	1.42mil		
6	Dielectric 3	FR-4	32.00mil	4.2	
7	Signal Layer 1	Copper	1.42mil		
8	Dielectric 4	FR-4	12.00mil	4.2	
9	Solder Side	Copper	1.42mil		
10	Bottom Solder	Solder Resist	0.40mil	3.5	
11	Bottom Overlay				

DESIGN INFORMATION

MIN. TRACK WIDTH: 8 MIL

MIN. CLEARANCE: 0.2 mm

MIN. VIA PAD SIZE: 24 MIL

MINIMUM ANNULAR RING 0.05mm (2MIL) EXTERNAL

PER IPC-D-275 CLASS 2 LEVEL C

REGISTRATION TOLERANCES: METAL +/- 5 MIL, HOLES +/- 3 MIL

HOLE SIZE TOLERANCE (UNLESS OTHERWISE SPECIFIED): +/- 3 MIL

MATERIAL:

[ ] FR-408 [X] FR-4 High Tg [ ] OTHER

THICKNESS: [X] 62 MIL (1.6mm) +/-10% [ ] OTHER

TOLERANCE: [X] ANSI IPC-6012 TYPE 3 CLASS 2

[ ] OTHER +/-

BOW & TWIST: [X] ANSI IPC-6012 TYPE 3 CLASS 2

[ ] OTHER +/-

DRILLING:

REFERENCE: [X] AS SHOWN [X] NC_DRILL FILES

PTH MIN COPPER THICKNESS: [X] 1MIL [ ] OTHER

BOARD FINISH:

SILKSCREEN: [X] TOP [X] BOTTOM

SILKSCREEN COLOR: [X] WHITE [ ] OTHER

SOLDER RESIST COLOR: [X] GREEN [ ] OTHER

[X] MATTE [ ] SEMI-GLOSS

SURFACE FINISH: [X] IMMERSION GOLD (ENIG) [ ] ENEPIG

[ ] IMM. TIN/SILVER OR EQUIV [ ] OTHER

ARRAY/PANEL: [ ] CUT AND TRIM PER M1 BOARD OUTLINE

[ ] N.C. ROUTE [X] V. SCORE

CERTIFICATION: MATERIALS AND WORKMANSHIP FOR ALL PCBS TO MEET OR EXCEED THE REQUIREMENTS OF:

[X] ANSI IPC-A-600F CLASS -> [ ] 1 [X] 2 [ ] 3

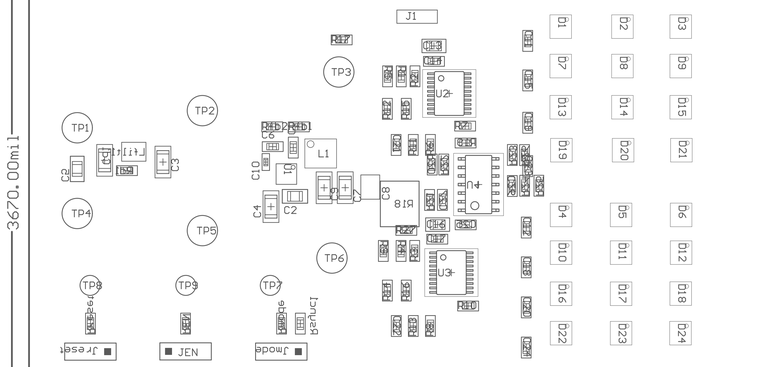
[X] UL 94V-0 [X] RoHS [ ] OTHER PER ORDER

ADDITIONAL REQUIREMENTS:

MICROSECTION: [ ] YES

BARE BOARD ELEC. TEST: [ ] NONE [X] REQUIRED [ ] PER ORDER

MANUFACTURER'S UL: [ ] RAIL [ ] METAL [X] SILK



COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.

ASSEMBLY VARIANT: [No Variations]

TEXAS INSTRUMENTS

PROJECT TITLE: LM53600NAEVM/O1LAEVM

DESIGNED FOR: Public Release

FILE NAME: TIDA01348.PcbDoc

PCB VIEWED FROM TOP SIDE	BOARD #: TIDA-01348	REV: A	SVN REV: Not In VersionControl
LAYER NAME =	TID #: TIDA-01348		
PLOT NAME = Mechanical 14	GENERATED : 9/26/2016 3:38:52 PM	TEXAS INSTRUMENTS	

ENGINEER: Robert Blattner	LAYOUT BY: Robert Blattner
SCALE: 1.00	ALTIUM DESIGNER VERSION: 16.0.9.368

Layer	Name	Material	Thickness	Constant	Board Layer Stack
1	Top Overlay				
2	Top Solder	Solder Resist	0.40mil	3.5	
3	Component Side	Copper	1.42mil		
4	Dielectric 1	FR-4	12.00mil	4.2	
5	Ground Plane	Copper	1.42mil		
6	Dielectric 3	FR-4	32.00mil	4.2	
7	Signal Layer 1	Copper	1.42mil		
8	Dielectric 4	FR-4	12.00mil	4.2	
9	Solder Side	Copper	1.42mil		
10	Bottom Solder	Solder Resist	0.40mil	3.5	
11	Bottom Overlay				

DESIGN INFORMATION

MIN. TRACK WIDTH: 8 MIL

MIN. CLEARANCE: 0.2 mm

MIN. VIA PAD SIZE: 24 MIL

MINIMUM ANNULAR RING 0.05mm (2MIL) EXTERNAL

PER IPC-D-275 CLASS 2 LEVEL C

REGISTRATION TOLERANCES: METAL +/- 5 MIL, HOLES +/- 3 MIL

HOLE SIZE TOLERANCE (UNLESS OTHERWISE SPECIFIED): +/- 3 MIL

MATERIAL:

[ ] FR-408 [X] FR-4 High Tg [ ] OTHER _____

THICKNESS: [X] 62 MIL (1.6mm) +/-10% [ ] OTHER _____

TOLERANCE: [X] ANSI IPC-6012 TYPE 3 CLASS 2

[ ] OTHER +/- _____

BOW & TWIST: [X] ANSI IPC-6012 TYPE 3 CLASS 2

[ ] OTHER +/- _____

DRILLING:

REFERENCE: [X] AS SHOWN [X] NC_DRILL FILES

PTH MIN COPPER THICKNESS: [X] 1MIL [ ] OTHER _____

BOARD FINISH:

SILKSCREEN: [X] TOP [X] BOTTOM

SILKSCREEN COLOR: [X] WHITE [ ] OTHER _____

SOLDER RESIST COLOR: [X] GREEN [ ] OTHER _____

[X] MATTE [ ] SEMI-GLOSS

SURFACE FINISH: [X] IMMERSION GOLD (ENIG) [ ] ENEPIG

[ ] IMM. TIN/SILVER OR EQUIV [ ] OTHER _____

ARRAY/PANEL: [ ] CUT AND TRIM PER M1 BOARD OUTLINE

[ ] N.C. ROUTE [X] V. SCORE

CERTIFICATION: MATERIALS AND WORKMANSHIP FOR ALL PCBS TO MEET OR EXCEED THE REQUIREMENTS OF:

[X] ANSI IPC-A-600F CLASS -> [ ] 1 [X] 2 [ ] 3

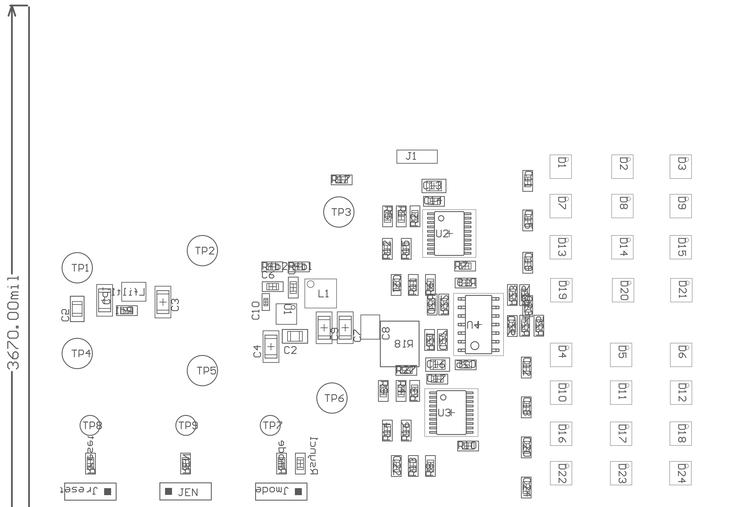
[X] UL 94V-0 [X] RoHS [ ] OTHER PER ORDER

ADDITIONAL REQUIREMENTS:

MICROSECTION: [ ] YES

BARE BOARD ELEC. TEST: [ ] NONE [X] REQUIRED [ ] PER ORDER

MANUFACTURER'S UL: [ ] RAIL [ ] METAL [X] SILK



COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.

ASSEMBLY VARIANT: [No Variations]

TEXAS INSTRUMENTS

PROJECT TITLE: LM53600NAEVM/O1LAEVM

DESIGNED FOR: Public Release

FILE NAME: TIDA01348.PcbDoc

PCB VIEWED FROM TOP SIDE	BOARD #: TIDA-01348	REV: A	SVN REV: Not In VersionControl
LAYER NAME =	TID #: TIDA-01348		
PLOT NAME = Mechanical 15	GENERATED : 9/26/2016 3:38:55 PM	TEXAS INSTRUMENTS	

ENGINEER: Robert Blattner	LAYOUT BY: Robert Blattner
SCALE: 1.00	ALTIUM DESIGNER VERSION: 16.0.9.368

Layer	Name	Material	Thickness	Constant	Board Layer Stack
1	Top Overlay				
2	Top Solder	Solder Resist	0.40mil	3.5	
3	Component Side	Copper	1.42mil		
4	Dielectric 1	FR-4	12.00mil	4.2	
5	Ground Plane	Copper	1.42mil		
6	Dielectric 3	FR-4	32.00mil	4.2	
7	Signal Layer 1	Copper	1.42mil		
8	Dielectric 4	FR-4	12.00mil	4.2	
9	Solder Side	Copper	1.42mil		
10	Bottom Solder	Solder Resist	0.40mil	3.5	
11	Bottom Overlay				

DESIGN INFORMATION

MIN. TRACK WIDTH: 8 MIL

MIN. CLEARANCE: 0.2 mm

MIN. VIA PAD SIZE: 24 MIL

MINIMUM ANNULAR RING 0.05mm (2MIL) EXTERNAL

PER IPC-D-275 CLASS 2 LEVEL C

REGISTRATION TOLERANCES: METAL +/- 5 MIL, HOLES +/- 3 MIL

HOLE SIZE TOLERANCE (UNLESS OTHERWISE SPECIFIED): +/- 3 MIL

MATERIAL:

[ ] FR-408 [X] FR-4 High Tg [ ] OTHER

THICKNESS: [X] 62 MIL (1.6mm) +/-10% [ ] OTHER

TOLERANCE: [X] ANSI IPC-6012 TYPE 3 CLASS 2

[ ] OTHER +/-

BOW & TWIST: [X] ANSI IPC-6012 TYPE 3 CLASS 2

[ ] OTHER +/-

DRILLING:

REFERENCE: [X] AS SHOWN [X] NC_DRILL FILES

PTH MIN COPPER THICKNESS: [X] 1MIL [ ] OTHER

BOARD FINISH:

SILKSCREEN: [X] TOP [X] BOTTOM

SILKSCREEN COLOR: [X] WHITE [ ] OTHER

SOLDER RESIST COLOR: [X] GREEN [ ] OTHER

[X] MATTE [ ] SEMI-GLOSS

SURFACE FINISH: [X] IMMERSION GOLD (ENIG) [ ] ENEPIG

[ ] IMM. TIN/SILVER OR EQUIV [ ] OTHER

ARRAY/PANEL: [ ] CUT AND TRIM PER M1 BOARD OUTLINE

[ ] N.C. ROUTE [X] V. SCORE

CERTIFICATION: MATERIALS AND WORKMANSHIP FOR ALL PCBS TO MEET OR EXCEED THE REQUIREMENTS OF:

[X] ANSI IPC-A-600F CLASS -> [ ] 1 [X] 2 [ ] 3

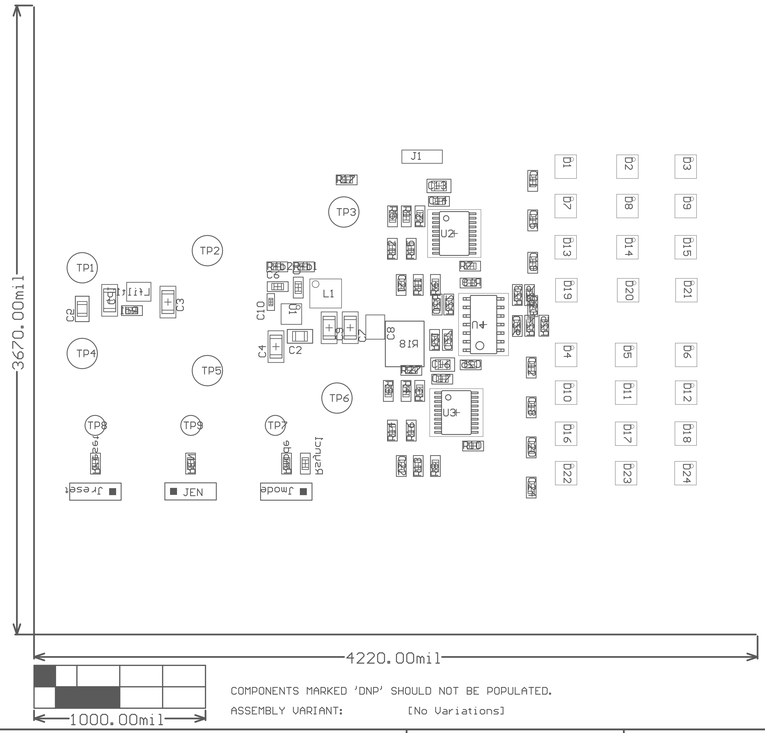
[X] UL 94V-0 [X] RoHS [ ] OTHER PER ORDER

ADDITIONAL REQUIREMENTS:

MICROSECTION: [ ] YES

BARE BOARD ELEC. TEST: [ ] NONE [X] REQUIRED [ ] PER ORDER

MANUFACTURER'S UL: [ ] RAIL [ ] METAL [X] SILK



COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.

ASSEMBLY VARIANT: [No Variations]

TEXAS INSTRUMENTS

PROJECT TITLE: LM53600NAEVM/01LAEVM

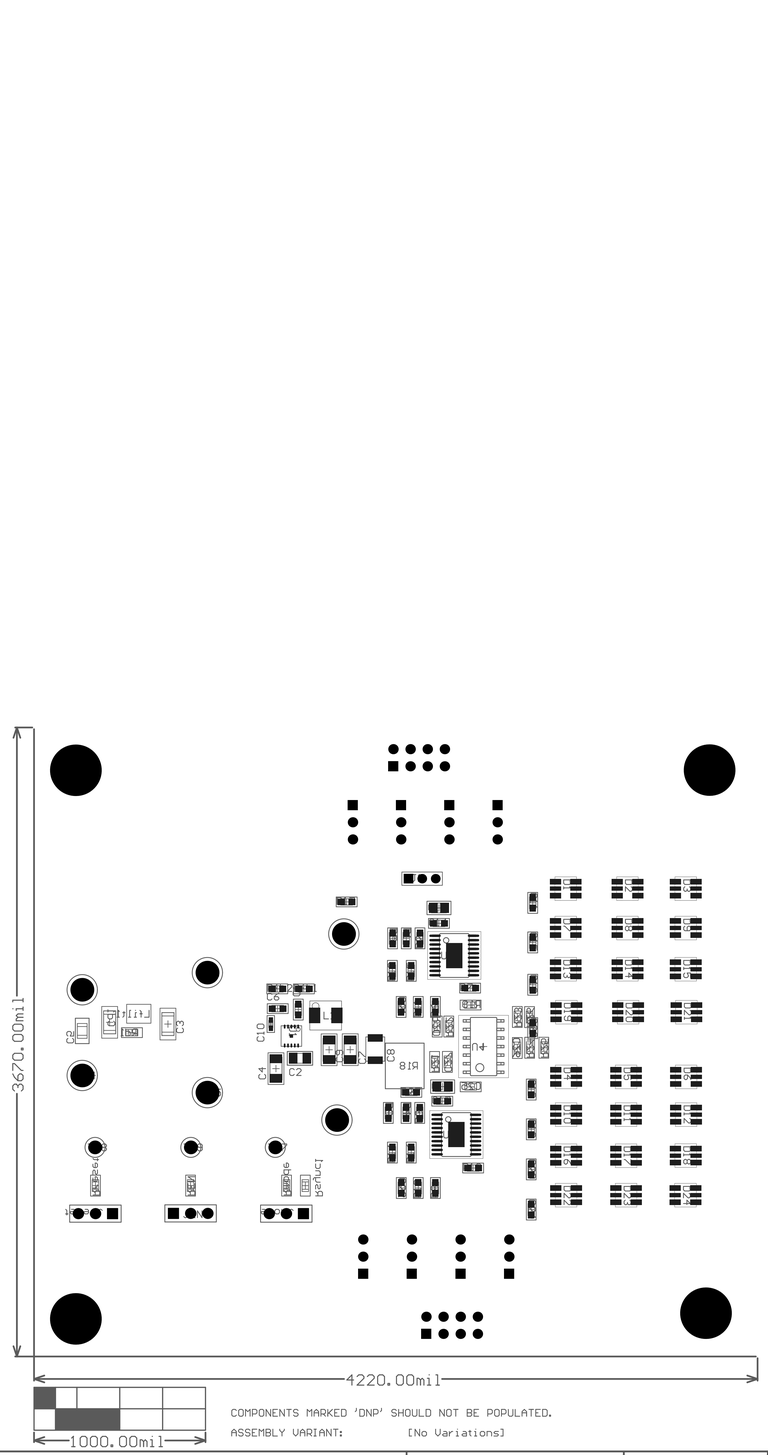
DESIGNED FOR: Public Release

FILE NAME: TIDA01348.PcbDoc

PCB VIEWED FROM TOP SIDE	BOARD #: TIDA-01348	REV: A	SVN REV: Not In VersionControl
LAYER NAME =	TID #: TIDA-01348		
PLOT NAME = Mechanical 16	GENERATED : 9/26/2016 3:38:58 PM	TEXAS INSTRUMENTS	

ENGINEER: Robert Blattner	LAYOUT BY: Robert Blattner
SCALE: 1.00	ALTIUM DESIGNER VERSION: 16.0.9.368

Layer	Name	Material	Thickness	Constant	Board Layer Stack
1	Top Overlay				
2	Top Solder	Solder Resist	0.40mil	3.5	
3	Component Side	Copper	1.42mil		
4	Dielectric 1	FR-4	12.00mil	4.2	
5	Ground Plane	Copper	1.42mil		
6	Dielectric 3	FR-4	32.00mil	4.2	
7	Signal Layer 1	Copper	1.42mil		
8	Dielectric 4	FR-4	12.00mil	4.2	
9	Solder Side	Copper	1.42mil		
10	Bottom Solder	Solder Resist	0.40mil	3.5	
11	Bottom Overlay				



COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.
ASSEMBLY VARIANT: [No Variations]

DESIGN INFORMATION

MIN. TRACK WIDTH: 8 MIL
MIN. CLEARANCE: 0.2 mm
MIN. VIA PAD SIZE: 24 MIL
MINIMUM ANNULAR RING 0.05mm (2MIL) EXTERNAL
PER IPC-D-275 CLASS 2 LEVEL C
REGISTRATION TOLERANCES: METAL +/- 5 MIL, HOLES +/- 3 MIL
HOLE SIZE TOLERANCE (UNLESS OTHERWISE SPECIFIED): +/- 3 MIL

MATERIAL:
[ ] FR-408 [X] FR-4 High Tg [ ] OTHER
THICKNESS: [X] 62 MIL (1.6mm) +/-10% [ ] OTHER
TOLERANCE: [X] ANSI IPC-6012 TYPE 3 CLASS 2
[ ] OTHER +/-
BOW & TWIST: [X] ANSI IPC-6012 TYPE 3 CLASS 2
[ ] OTHER +/-
DRILLING:
REFERENCE: [X] AS SHOWN [X] NC_DRILL FILES
PTH MIN COPPER THICKNESS: [X] 1MIL [ ] OTHER
BOARD FINISH:
SILKSCREEN: [X] TOP [X] BOTTOM
SILKSCREEN COLOR: [X] WHITE [ ] OTHER
SOLDER RESIST COLOR: [X] GREEN [ ] OTHER
[X] MATTE [ ] SEMI-GLOSS
SURFACE FINISH: [X] IMMERSION GOLD (ENIG) [ ] ENEPIG
[ ] IMM. TIN/SILVER OR EQUIV [ ] OTHER
ARRAY/PANEL: [ ] CUT AND TRIM PER M1 BOARD OUTLINE
[ ] N.C. ROUTE [X] V. SCORE
CERTIFICATION: MATERIALS AND WORKMANSHIP FOR ALL PCBS TO MEET OR EXCEED THE REQUIREMENTS OF:
[X] ANSI IPC-A-600F CLASS -> [ ] 1 [X] 2 [ ] 3
[X] UL 94V-0 [X] RoHS [ ] OTHER PER ORDER
ADDITIONAL REQUIREMENTS:
MICROSECTION: [ ] YES
BARE BOARD ELEC. TEST: [ ] NONE [X] REQUIRED [ ] PER ORDER
MANUFACTURER'S UL: [ ] RAIL [ ] METAL [X] SILK

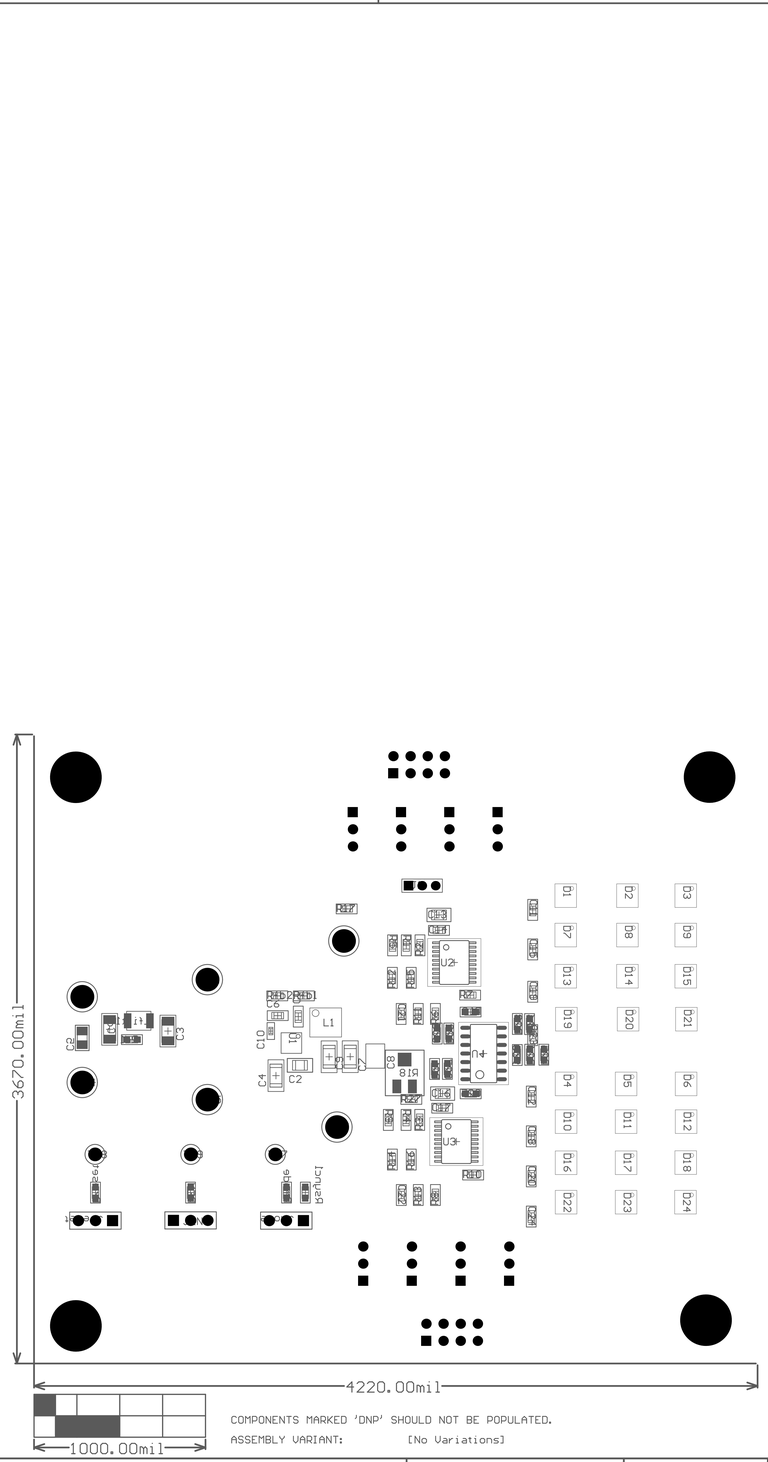
TEXAS INSTRUMENTS

PROJECT TITLE: LM5360ONAEVM/O1LAEVM
DESIGNED FOR: Public Release
FILE NAME: TIDA01348.PcbDoc

PCB VIEWED FROM TOP SIDE	BOARD #: TIDA-01348	REV: A	SVN REV: Not In VersionControl
LAYER NAME =	TID #: TIDA-01348		
PLOT NAME = Top Pad Master	GENERATED : 9/26/2016 3:39:02 PM	TEXAS INSTRUMENTS	

ENGINEER:	LAYOUT BY:
Robert Blattner	Robert Blattner
SCALE: 1.00	ALTIUM DESIGNER VERSION: 16.0.9.368

Layer	Name	Material	Thickness	Constant	Board Layer Stack
1	Top Overlay				
2	Top Solder	Solder Resist	0.40mil	3.5	
3	Component Side	Copper	1.42mil		
4	Dielectric 1	FR-4	12.00mil	4.2	
5	Ground Plane	Copper	1.42mil		
6	Dielectric 3	FR-4	32.00mil	4.2	
7	Signal Layer 1	Copper	1.42mil		
8	Dielectric 4	FR-4	12.00mil	4.2	
9	Solder Side	Copper	1.42mil		
10	Bottom Solder	Solder Resist	0.40mil	3.5	
11	Bottom Overlay				



COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.
ASSEMBLY VARIANT: [No Variations]

DESIGN INFORMATION

MIN. TRACK WIDTH: 8 MIL
MIN. CLEARANCE: 0.2 mm
MIN. VIA PAD SIZE: 24 MIL
MINIMUM ANNULAR RING 0.05mm (2MIL) EXTERNAL
PER IPC-D-275 CLASS 2 LEVEL C
REGISTRATION TOLERANCES: METAL +/- 5 MIL, HOLES +/- 3 MIL
HOLE SIZE TOLERANCE (UNLESS OTHERWISE SPECIFIED): +/- 3 MIL

MATERIAL:
[ ] FR-408 [X] FR-4 High Tg [ ] OTHER _____
THICKNESS: [X] 62 MIL (1.6mm) +/-10% [ ] OTHER _____
TOLERANCE: [X] ANSI IPC-6012 TYPE 3 CLASS 2
[ ] OTHER +/- _____
BOW & TWIST: [X] ANSI IPC-6012 TYPE 3 CLASS 2
[ ] OTHER +/- _____

DRILLING:
REFERENCE: [X] AS SHOWN [X] NC_DRILL FILES
PTH MIN COPPER THICKNESS: [X] 1MIL [ ] OTHER _____

BOARD FINISH:
SILKSCREEN: [X] TOP [X] BOTTOM
SILKSCREEN COLOR: [X] WHITE [ ] OTHER _____
SOLDER RESIST COLOR: [X] GREEN [ ] OTHER _____
[X] MATTE [ ] SEMI-GLOSS

SURFACE FINISH: [X] IMMERSION GOLD (ENIG) [ ] ENEPIG
[ ] IMM. TIN/SILVER OR EQUIV [ ] OTHER _____

ARRAY/PANEL: [ ] CUT AND TRIM PER M1 BOARD OUTLINE
[ ] N.C. ROUTE [X] V. SCORE

CERTIFICATION: MATERIALS AND WORKMANSHIP FOR ALL PCBS TO MEET OR EXCEED THE REQUIREMENTS OF:
[X] ANSI IPC-A-600F CLASS -> [ ] 1 [X] 2 [ ] 3
[X] UL 94V-0 [X] RoHS [ ] OTHER PER ORDER

ADDITIONAL REQUIREMENTS:
MICROSECTION: [ ] YES
BARE BOARD ELEC. TEST: [ ] NONE [X] REQUIRED [ ] PER ORDER
MANUFACTURER'S UL: [ ] RAIL [ ] METAL [X] SILK

TEXAS INSTRUMENTS

PROJECT TITLE: LM5360ONAEVM/O1LAEVM
DESIGNED FOR: Public Release
FILE NAME: TIDA01348.PcbDoc

PCB VIEWED FROM TOP SIDE	BOARD #: TIDA-01348	REV: A	SVN REV: Not In VersionControl
LAYER NAME =	TID #: TIDA-01348		
PLOT NAME = Bottom Pad Master	GENERATED : 9/26/2016 3:39:05 PM	TEXAS INSTRUMENTS	

ENGINEER: Robert Blattner	LAYOUT BY: Robert Blattner
SCALE: 1.00	ALTIUM DESIGNER VERSION: 16.0.9.368

Layer	Name	Material	Thickness	Constant	Board Layer Stack
1	Top Overlay				
2	Top Solder	Solder Resist	0.40mil	3.5	
3	Component Side	Copper	1.42mil		
4	Dielectric 1	FR-4	12.00mil	4.2	
5	Ground Plane	Copper	1.42mil		
6	Dielectric 3	FR-4	32.00mil	4.2	
7	Signal Layer 1	Copper	1.42mil		
8	Dielectric 4	FR-4	12.00mil	4.2	
9	Solder Side	Copper	1.42mil		
10	Bottom Solder	Solder Resist	0.40mil	3.5	
11	Bottom Overlay				

DESIGN INFORMATION

MIN. TRACK WIDTH: 8 MIL

MIN. CLEARANCE: 0.2 mm

MIN. VIA PAD SIZE: 24 MIL

MINIMUM ANNULAR RING 0.05mm (2MIL) EXTERNAL

PER IPC-D-275 CLASS 2 LEVEL C

REGISTRATION TOLERANCES: METAL +/- 5 MIL, HOLES +/- 3 MIL

HOLE SIZE TOLERANCE (UNLESS OTHERWISE SPECIFIED): +/- 3 MIL

MATERIAL:

[ ] FR-408 [X] FR-4 High Tg [ ] OTHER _____

THICKNESS: [X] 62 MIL (1.6mm) +/-10% [ ] OTHER _____

TOLERANCE: [X] ANSI IPC-6012 TYPE 3 CLASS 2

[ ] OTHER +/- _____

BOW & TWIST: [X] ANSI IPC-6012 TYPE 3 CLASS 2

[ ] OTHER +/- _____

DRILLING:

REFERENCE: [X] AS SHOWN [X] NC_DRILL FILES

PTH MIN COPPER THICKNESS: [X] 1MIL [ ] OTHER _____

BOARD FINISH:

SILKSCREEN: [X] TOP [X] BOTTOM

SILKSCREEN COLOR: [X] WHITE [ ] OTHER _____

SOLDER RESIST COLOR: [X] GREEN [ ] OTHER _____

[X] MATTE [ ] SEMI-GLOSS

SURFACE FINISH: [X] IMMERSION GOLD (ENIG) [ ] ENEPIG

[ ] IMM. TIN/SILVER OR EQUIV [ ] OTHER _____

ARRAY/PANEL: [ ] CUT AND TRIM PER M1 BOARD OUTLINE

[ ] N.C. ROUTE [X] V. SCORE

CERTIFICATION: MATERIALS AND WORKMANSHIP FOR ALL PCBS TO MEET OR EXCEED THE REQUIREMENTS OF:

[X] ANSI IPC-A-600F CLASS -> [ ] 1 [X] 2 [ ] 3

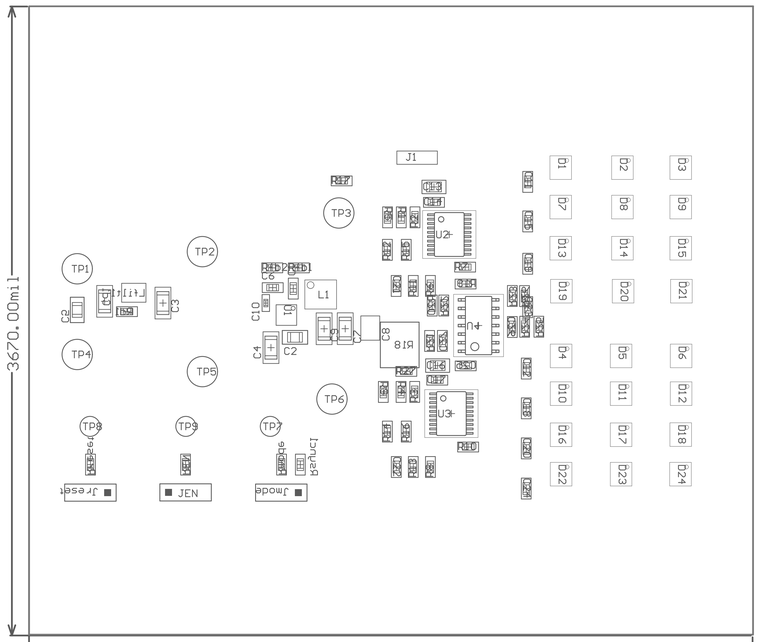
[X] UL 94V-0 [X] RoHS [ ] OTHER PER ORDER

ADDITIONAL REQUIREMENTS:

MICROSECTION: [ ] YES

BARE BOARD ELEC. TEST: [ ] NONE [X] REQUIRED [ ] PER ORDER

MANUFACTURER'S UL: [ ] RAIL [ ] METAL [X] SILK



COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.

ASSEMBLY VARIANT: [No Variations]

TEXAS INSTRUMENTS

PROJECT TITLE: LM53600NAEVM/O1LAEVM

DESIGNED FOR: Public Release

FILE NAME: TIDA01348.PcbDoc

PCB VIEWED FROM TOP SIDE	BOARD #: TIDA-01348	REV: A	SUN REV: Not In VersionControl	
LAYER NAME =	TID #: TIDA-01348			
PLOT NAME = Keep Out Layer	GENERATED : 9/26/2016 3:39:08 PM		TEXAS INSTRUMENTS	

ENGINEER: Robert Blattner	LAYOUT BY: Robert Blattner
SCALE: 1.00	ALTIUM DESIGNER VERSION: 16.0.9.368

Layer	Name	Material	Thickness	Constant	Board Layer Stack
1	Top Overlay				
2	Top Solder	Solder Resist	0.40mil	3.5	
3	Component Side	Copper	1.42mil		
4	Dielectric 1	FR-4	12.00mil	4.2	
5	Ground Plane	Copper	1.42mil		
6	Dielectric 3	FR-4	32.00mil	4.2	
7	Signal Layer 1	Copper	1.42mil		
8	Dielectric 4	FR-4	12.00mil	4.2	
9	Solder Side	Copper	1.42mil		
10	Bottom Solder	Solder Resist	0.40mil	3.5	
11	Bottom Overlay				

DESIGN INFORMATION

MIN. TRACK WIDTH: 8 MIL

MIN. CLEARANCE: 0.2 mm

MIN. VIA PAD SIZE: 24 MIL

MINIMUM ANNULAR RING 0.05mm (2MIL) EXTERNAL

PER IPC-D-275 CLASS 2 LEVEL C

REGISTRATION TOLERANCES: METAL +/- 5 MIL, HOLES +/- 3 MIL

HOLE SIZE TOLERANCE (UNLESS OTHERWISE SPECIFIED): +/- 3 MIL

MATERIAL:

[ ] FR-408 [X] FR-4 High Tg [ ] OTHER

THICKNESS: [X] 62 MIL (1.6mm) +/-10% [ ] OTHER

TOLERANCE: [X] ANSI IPC-6012 TYPE 3 CLASS 2

[ ] OTHER +/-

BOW & TWIST: [X] ANSI IPC-6012 TYPE 3 CLASS 2

[ ] OTHER +/-

DRILLING:

REFERENCE: [X] AS SHOWN [X] NC_DRILL FILES

PTH MIN COPPER THICKNESS: [X] 1MIL [ ] OTHER

BOARD FINISH:

SILKSCREEN: [X] TOP [X] BOTTOM

SILKSCREEN COLOR: [X] WHITE [ ] OTHER

SOLDER RESIST COLOR: [X] GREEN [ ] OTHER

[X] MATTE [ ] SEMI-GLOSS

SURFACE FINISH: [X] IMMERSION GOLD (ENIG) [ ] ENEPIG

[ ] IMM. TIN/SILVER OR EQUIV [ ] OTHER

ARRAY/PANEL: [ ] CUT AND TRIM PER M1 BOARD OUTLINE

[ ] N.C. ROUTE [X] V. SCORE

CERTIFICATION: MATERIALS AND WORKMANSHIP FOR ALL PCBS TO MEET OR EXCEED THE REQUIREMENTS OF:

[X] ANSI IPC-A-600F CLASS -> [ ] 1 [X] 2 [ ] 3

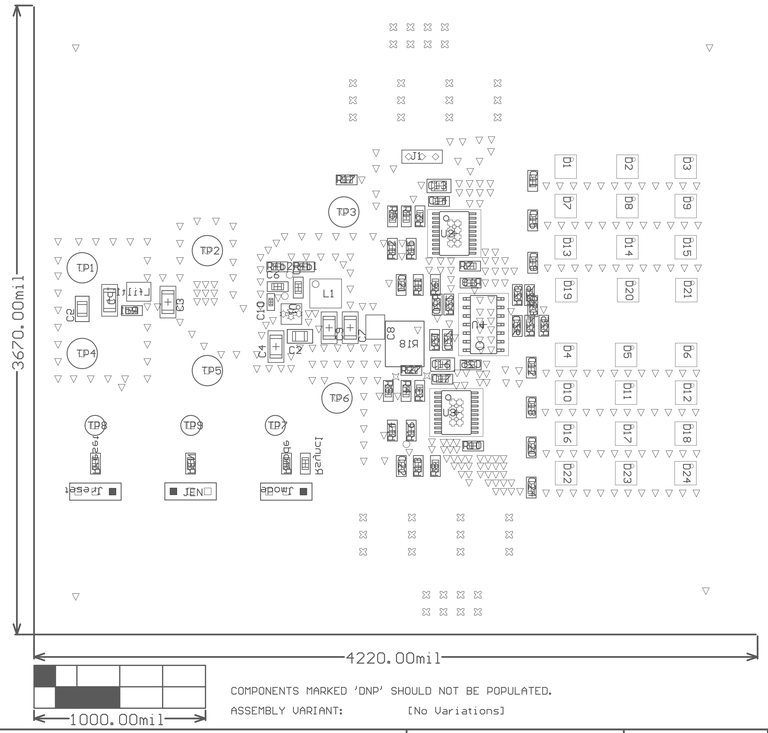
[X] UL 94V-0 [X] RoHS [ ] OTHER PER ORDER

ADDITIONAL REQUIREMENTS:

MICROSECTION: [ ] YES

BARE BOARD ELEC. TEST: [ ] NONE [X] REQUIRED [ ] PER ORDER

MANUFACTURER'S UL: [ ] RAIL [ ] METAL [X] SILK



Symbol	Quantity	Finished Hole Size	Plated	Hole Type
○	4	7,87mil (0,200mm)	PTH	Round
⊠	165	12,00mil (0,305mm)	PTH	Round
▽	12	40,00mil (1,016mm)	PTH	Round
☼	6	98,43mil (2,500mm)	PTH	Round
□	4	125,98mil (3,200mm)	PTH	Round
	191 Total			

COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.

ASSEMBLY VARIANT: [No Variations]

TEXAS INSTRUMENTS

PROJECT TITLE: LM5360ONAEVM/O1LAEVM

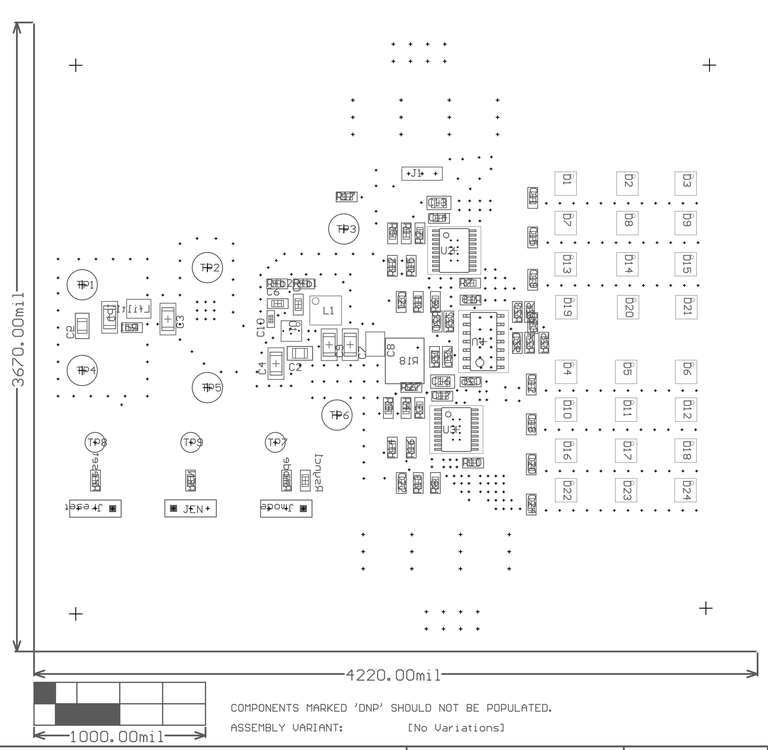
DESIGNED FOR: Public Release

FILE NAME: TIDA01348.PcbDoc

PCB VIEWED FROM TOP SIDE	BOARD #: TIDA-01348	REV: A	SVN REV: Not In VersionControl	
LAYER NAME =	TID #: TIDA-01348			
PLOT NAME = Drill Drawing For (Solder Side,Component Side)	GENERATED : 9/26/2016 3:39:12 PM		TEXAS INSTRUMENTS	

ENGINEER:	LAYOUT BY:
Robert Blattner	Robert Blattner
SCALE: 1.00	ALTIUM DESIGNER VERSION: 16.0.9.368

Layer	Name	Material	Thickness	Constant	Board Layer Stack
1	Top Overlay				
2	Top Solder	Solder Resist	0.40mil	3.5	
3	Component Side	Copper	1.42mil		
4	Dielectric 1	FR-4	12.00mil	4.2	
5	Ground Plane	Copper	1.42mil		
6	Dielectric 3	FR-4	32.00mil	4.2	
7	Signal Layer 1	Copper	1.42mil		
8	Dielectric 4	FR-4	12.00mil	4.2	
9	Solder Side	Copper	1.42mil		
10	Bottom Solder	Solder Resist	0.40mil	3.5	
11	Bottom Overlay				



COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.
ASSEMBLY VARIANT: [No Variations]

DESIGN INFORMATION

MIN. TRACK WIDTH: 8 MIL
MIN. CLEARANCE: 0.2 mm
MIN. VIA PAD SIZE: 24 MIL
MINIMUM ANNULAR RING 0.05mm (2MIL) EXTERNAL
PER IPC-D-275 CLASS 2 LEVEL C
REGISTRATION TOLERANCES: METAL +/- 5 MIL, HOLES +/- 3 MIL
HOLE SIZE TOLERANCE (UNLESS OTHERWISE SPECIFIED): +/- 3 MIL

MATERIAL:
[ ] FR-408 [X] FR-4 High Tg [ ] OTHER
THICKNESS: [X] 62 MIL (1.6mm) +/-10% [ ] OTHER
TOLERANCE: [X] ANSI IPC-6012 TYPE 3 CLASS 2
[ ] OTHER +/-
BOW & TWIST: [X] ANSI IPC-6012 TYPE 3 CLASS 2
[ ] OTHER +/-

DRILLING:
REFERENCE: [X] AS SHOWN [X] NC_DRILL FILES
PTH MIN COPPER THICKNESS: [X] 1MIL [ ] OTHER

BOARD FINISH:
SILKSCREEN: [X] TOP [X] BOTTOM
SILKSCREEN COLOR: [X] WHITE [ ] OTHER
SOLDER RESIST COLOR: [X] GREEN [ ] OTHER
[X] MATTE [ ] SEMI-GLOSS
SURFACE FINISH: [X] IMMERSION GOLD (ENIG) [ ] ENEPIG
[ ] IMM. TIN/SILVER OR EQUIV [ ] OTHER
ARRAY/PANEL: [ ] CUT AND TRIM PER M1 BOARD OUTLINE
[ ] N.C. ROUTE [X] V. SCORE
CERTIFICATION: MATERIALS AND WORKMANSHIP FOR ALL PCBS TO MEET OR EXCEED THE REQUIREMENTS OF:
[X] ANSI IPC-A-600F CLASS -> [ ] 1 [X] 2 [ ] 3
[X] UL 94V-0 [X] RoHS [ ] OTHER PER ORDER
ADDITIONAL REQUIREMENTS:
MICROSECTION: [ ] YES
BARE BOARD ELEC. TEST: [ ] NONE [X] REQUIRED [ ] PER ORDER
MANUFACTURER'S UL: [ ] RAIL [ ] METAL [X] SILK

TEXAS INSTRUMENTS

PROJECT TITLE: LM53600NAEVM/01LAEVM
DESIGNED FOR: Public Release
FILE NAME: TIDA01348.PcbDoc

PCB VIEWED FROM TOP SIDE	BOARD #: TIDA-01348	REV: A	SVN REV: Not In VersionControl
LAYER NAME =	TID #: TIDA-01348		
PLOT NAME = Drill Guide For (Solder Side,Component Side)	GENERATED : 9/26/2016 3:39:18 PM		TEXAS INSTRUMENTS

ENGINEER:	LAYOUT BY:
Robert Blattner	Robert Blattner
SCALE: 1.00	ALTIUM DESIGNER VERSION: 16.0.9.368

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